



Design and Development of Radiation Hardened Application-Specific Integrated Circuit for the ATHENA Mission

APC PhD Day - November 15, 2017

Si CHEN

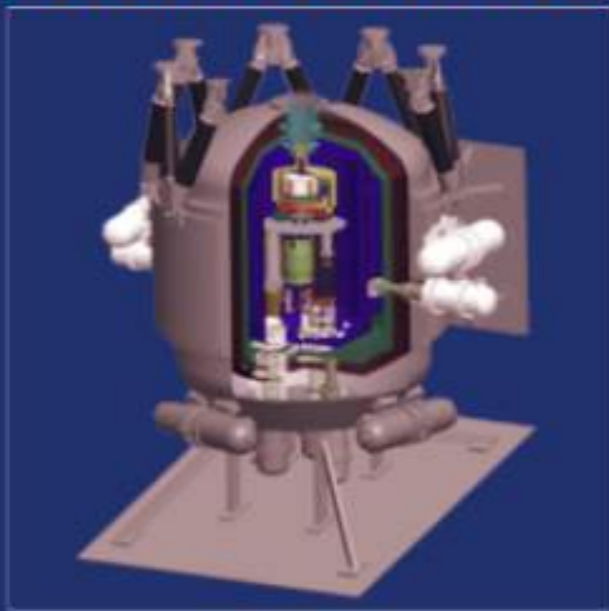
Advisor: Damien PRÊLE



Next Generation X-Ray Space Observatory of ESA

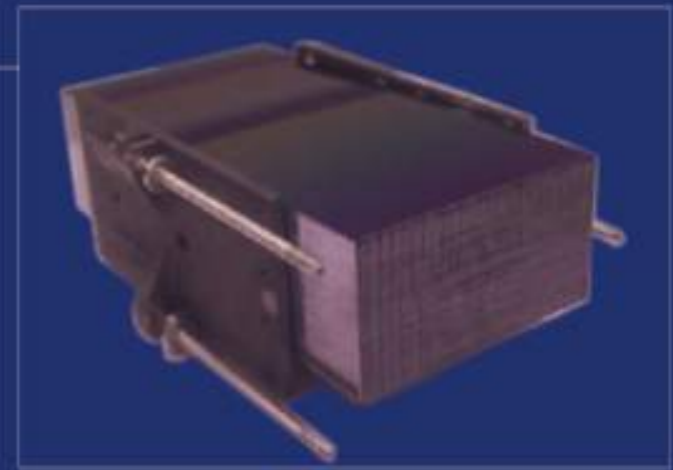
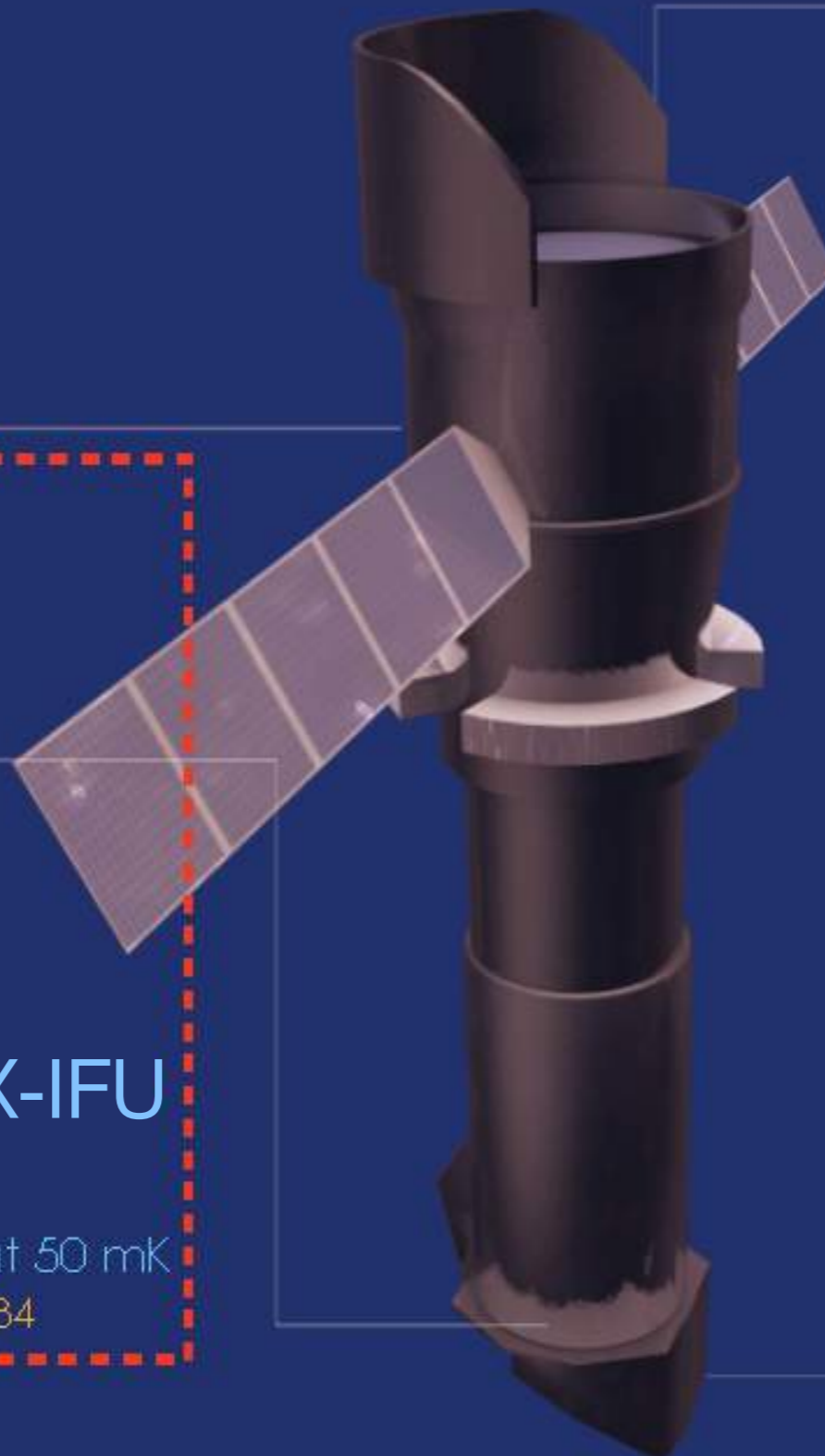
Ariane V class launcher

Satellite mass ~ 5500 kg
Power ~ 5600 W
Focal length: 12 m
Lifetime: 5 years (10 years)



X-ray Integral Field Unit: X-IFU

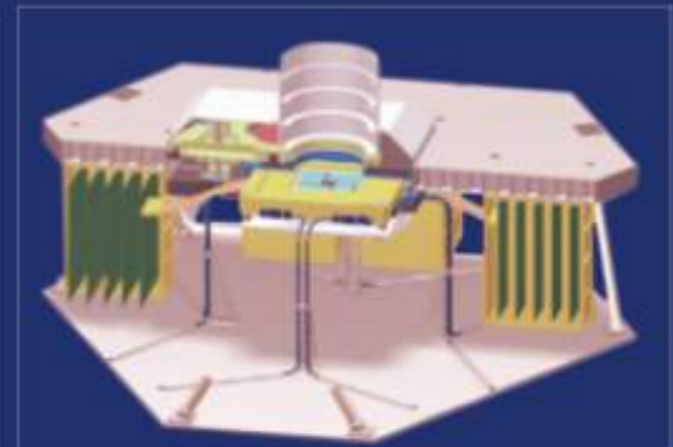
ΔE : 2.5 eV
Field of view: 5 arcmin
Large array of TES cooled at 50 mK
Barret et al. 2013 arXiv:1308.6784



Silicon Pore Optics:

Effective area: 2m² @ 1 keV
PSF (HEW): 5''

Willingale et al. 2013 arXiv1308.6785

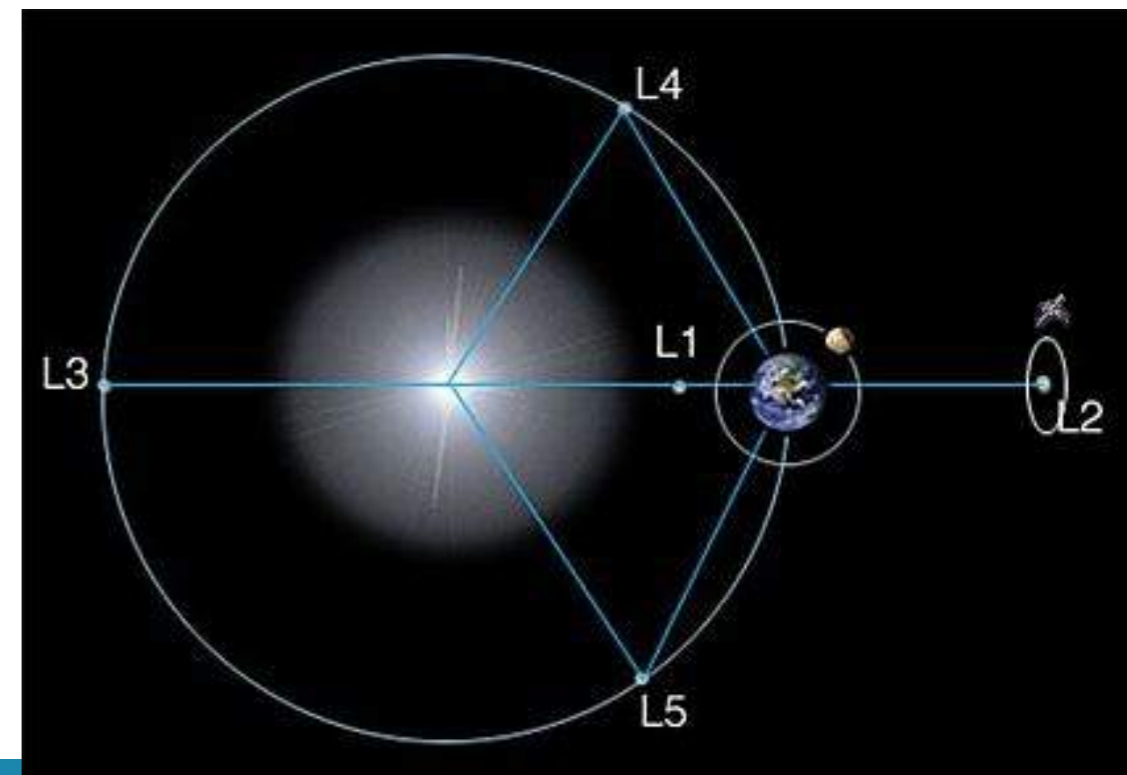


Wide Field Imager: WFI

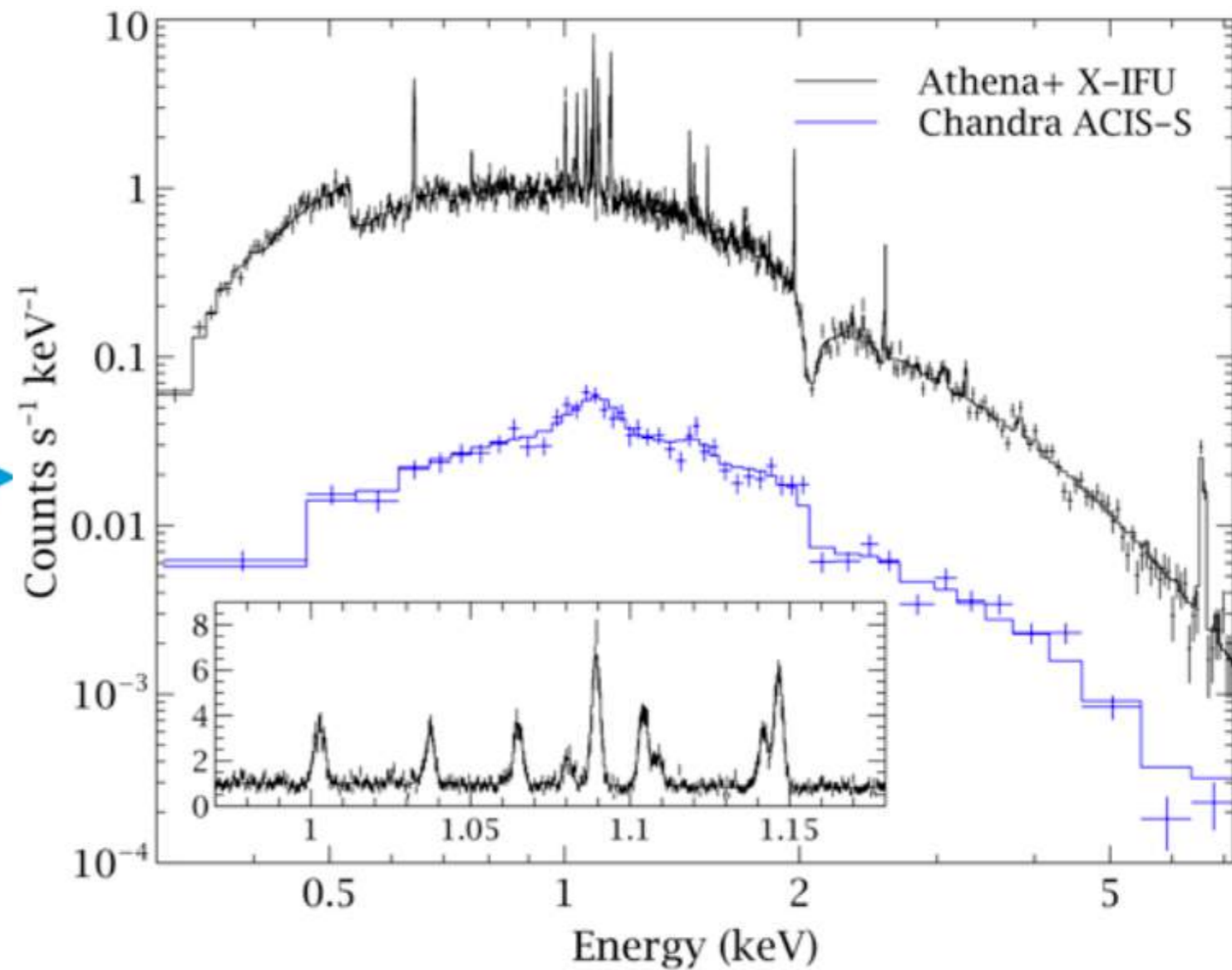
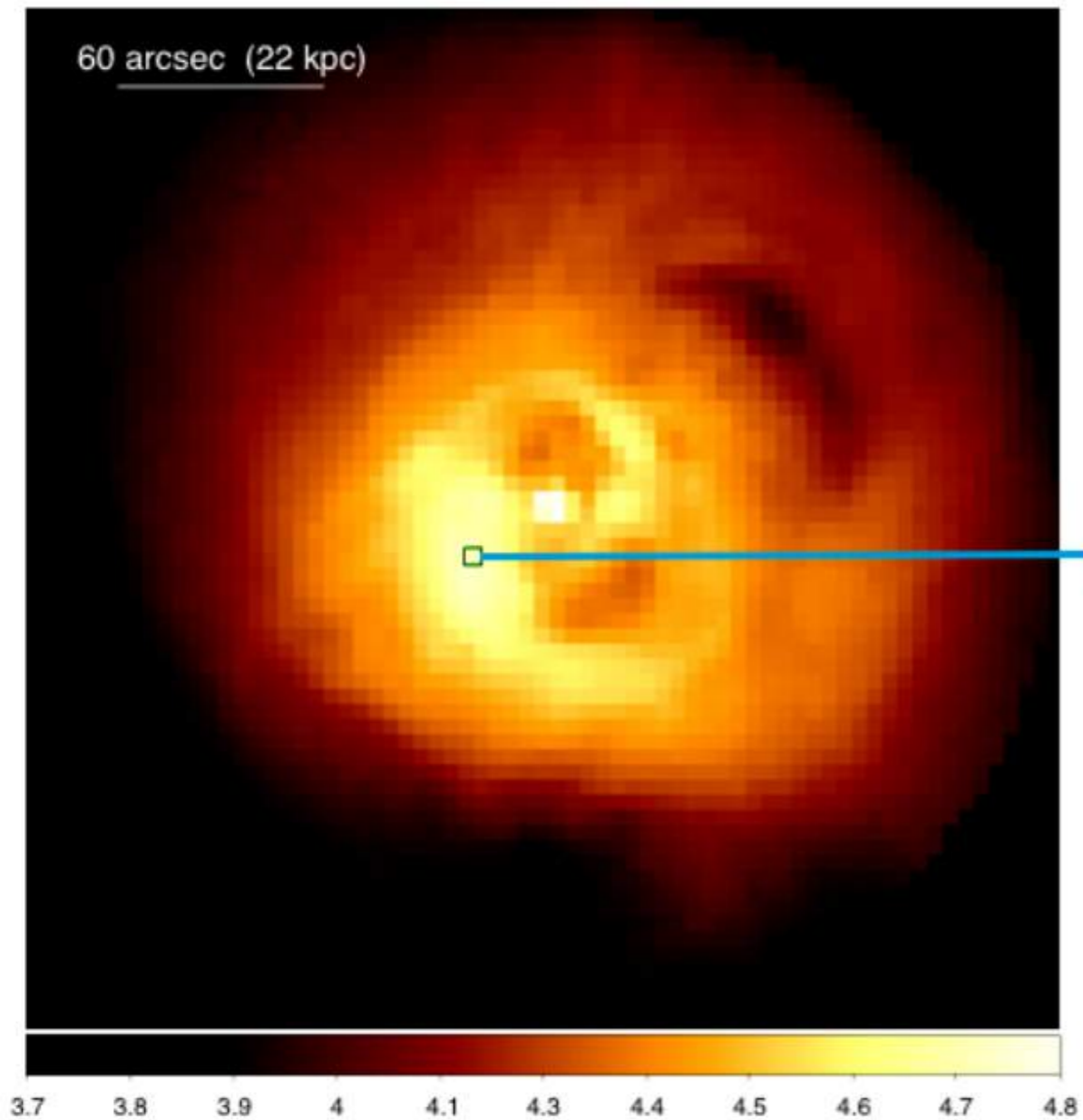
ΔE : 125 eV
Field of view: 40' x 40'
Rau et al. 2013 arXiv1307.1709



- « Hot and Energetic Universe science » theme
 - How does ordinary matter assemble into the large-scale structures we see in the Universe today?
 - How do black holes grow and shape the Universe?
- 0.5-12keV range
- L-class mission , 5 years lifetime, Launch date: 2028-2030
- Halo orbit around Lagrange point L2,



Simulation of a 50 ks X-IFU exposure of the Perseus cluster



Croston, Sanders et al. (2013, Athena+ Supporting Paper)

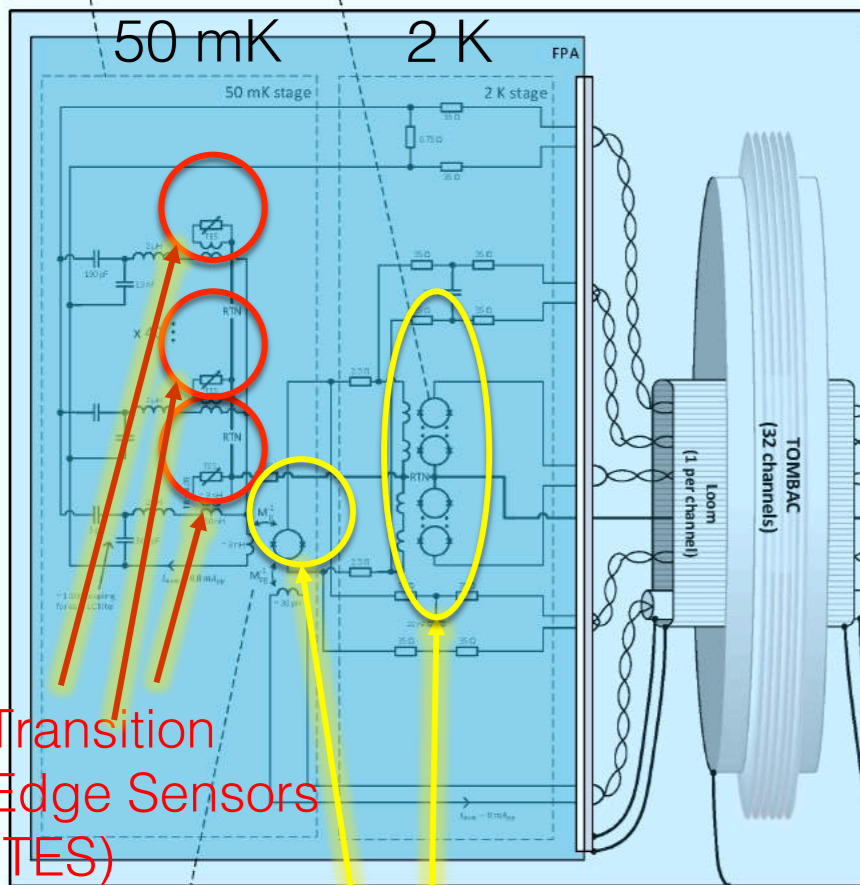
- Frequency-Division Multiplexing(FDM) 1-6 MHz, factor 40
- Matrix of 3840 TES /40 = 96 readout channels

FPA:Focal plane assembly

50mK - 2K cables properties:

- Len ~ 20 cm
- Z0 ~ 70 Ω
- Rdc = 0 Ω

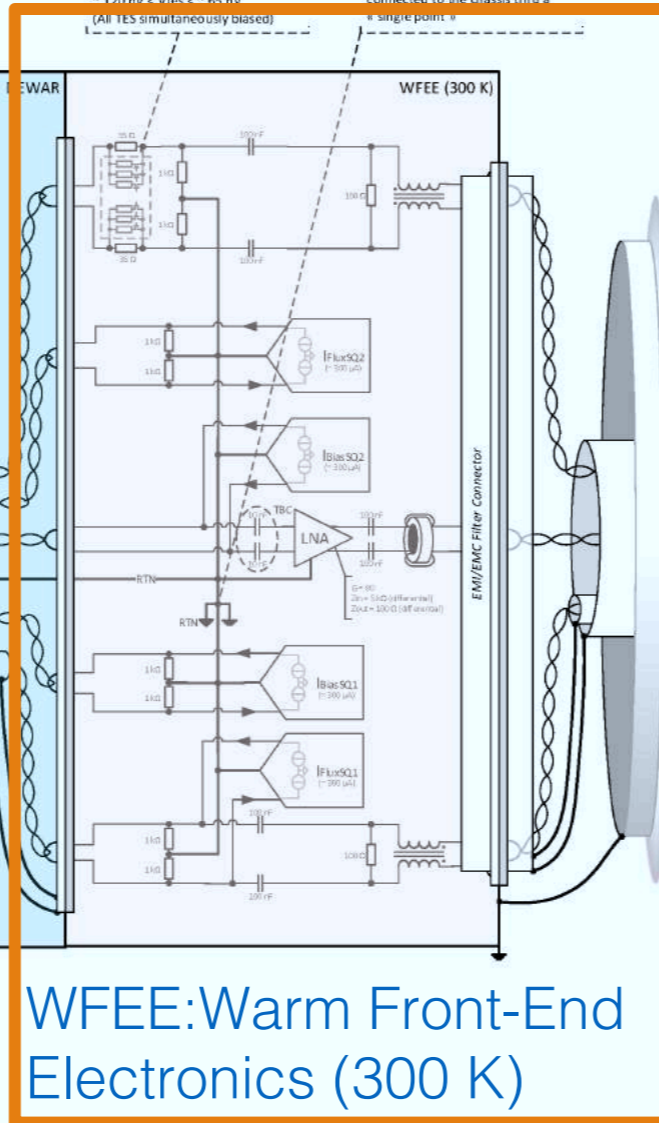
SQUID array output impedance ~ 100 Ω



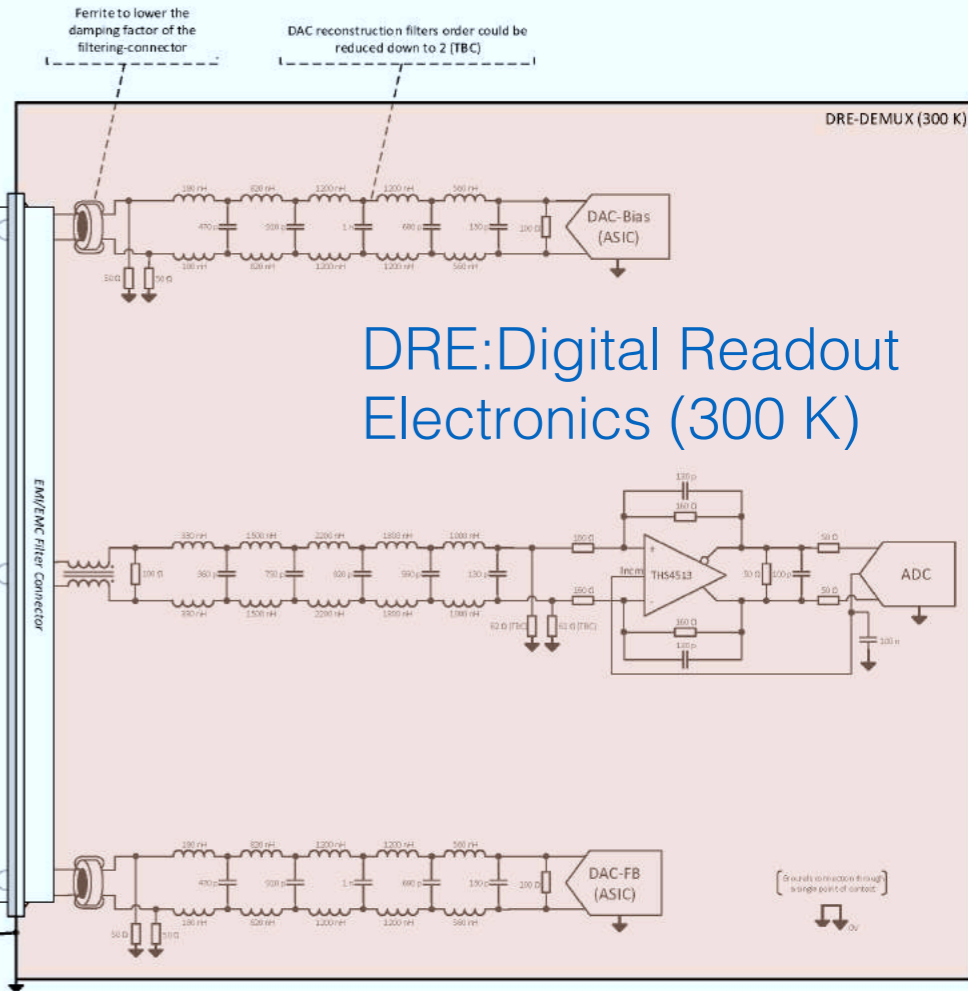
Observation mode:

- R = 70 Ω (all switches are off)
- Resistance swing:
 - 1 < R < 35 Ω
 - ~ 120 nV < Vtes < ~ 65 nV
 - (All TES simultaneously biased)

All RTNs inside a WFEE box are connected to the chassis thru a single point



WFEE:Warm Front-End Electronics (300 K)



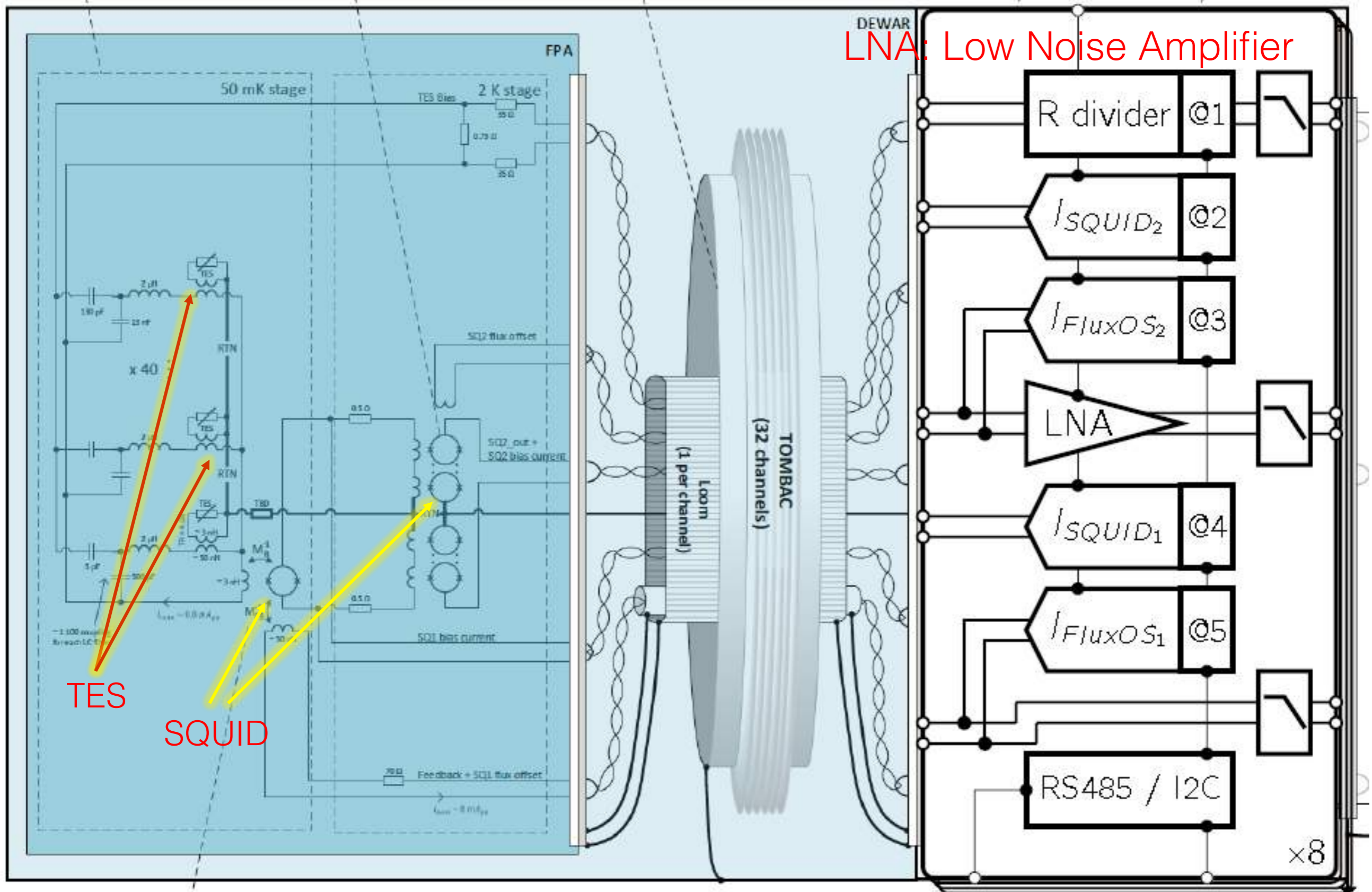
DRE:Digital Readout Electronics (300 K)

Transition Edge Sensors (TES)

* see SRON-XIFU-TN-2016-022

	Title: X-IFU Readout chain diagram			
	Project: ATHENA X-IFU			
	Author: CLENETA,	Ed.: 0	Rev.: 9	
	Date: 12/06/2017	Format: custom	Page	1/1

SQUID:Superconducting QUantum Interference Device

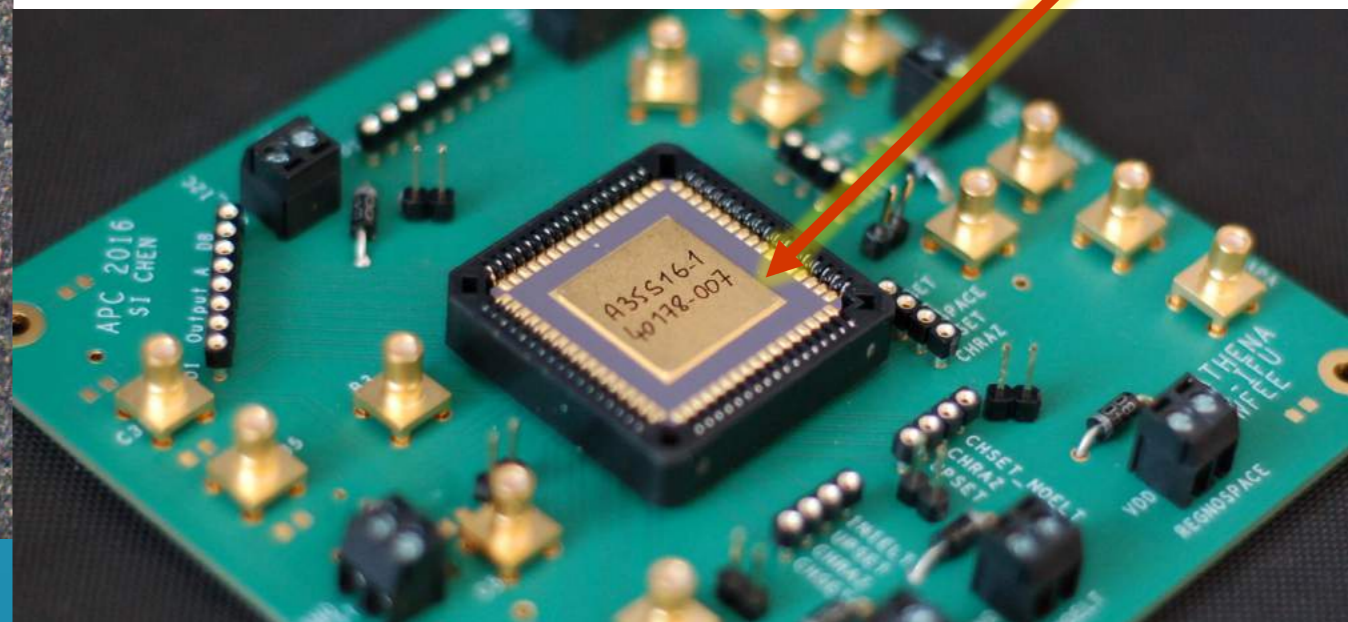
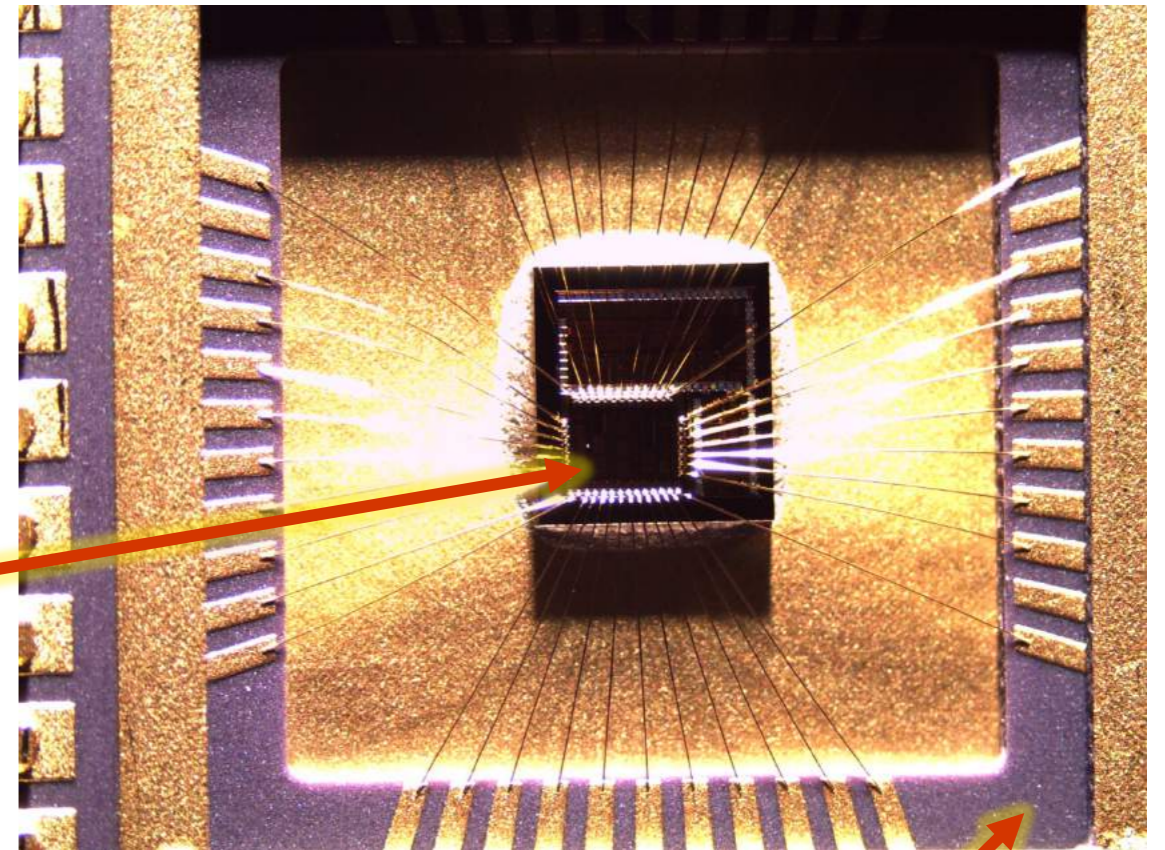
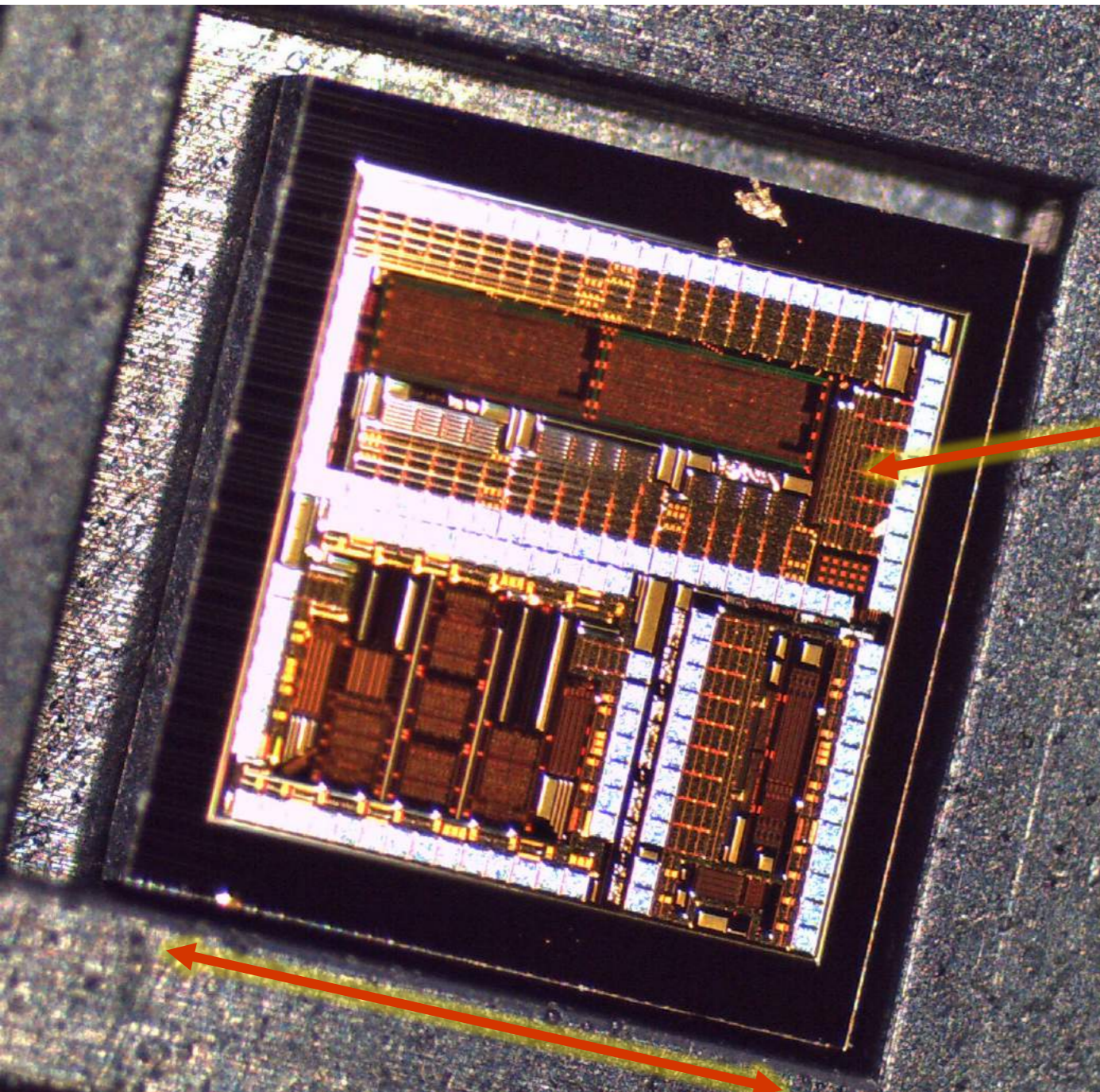




First ASIC AwaXe_V1 dedicated to WFEE



- AMS 350nm BiCMOS SiGe technology: BJT+MOS, good TID (Total Ionizing Dose) tolerance, widely used in space instrumentation, reliable
- ASIC: Application-specific integrated circuit

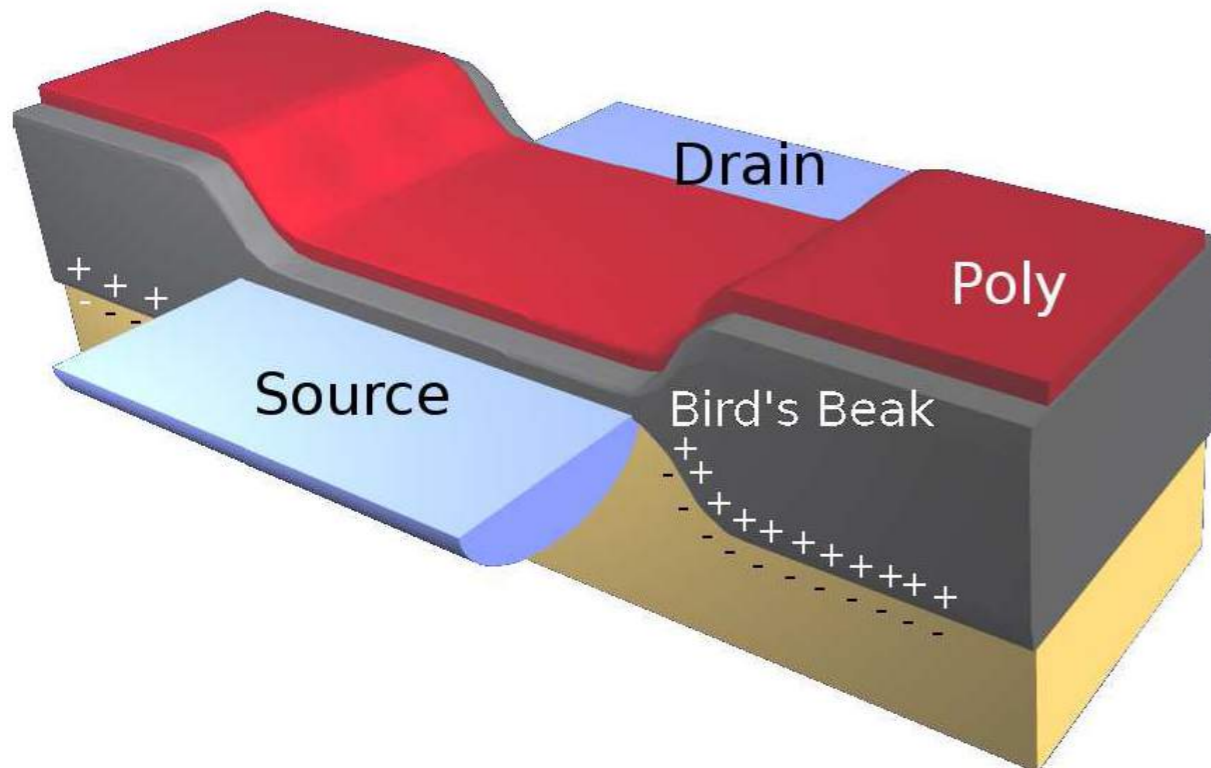


↔ $\approx 2.4\text{mm}$

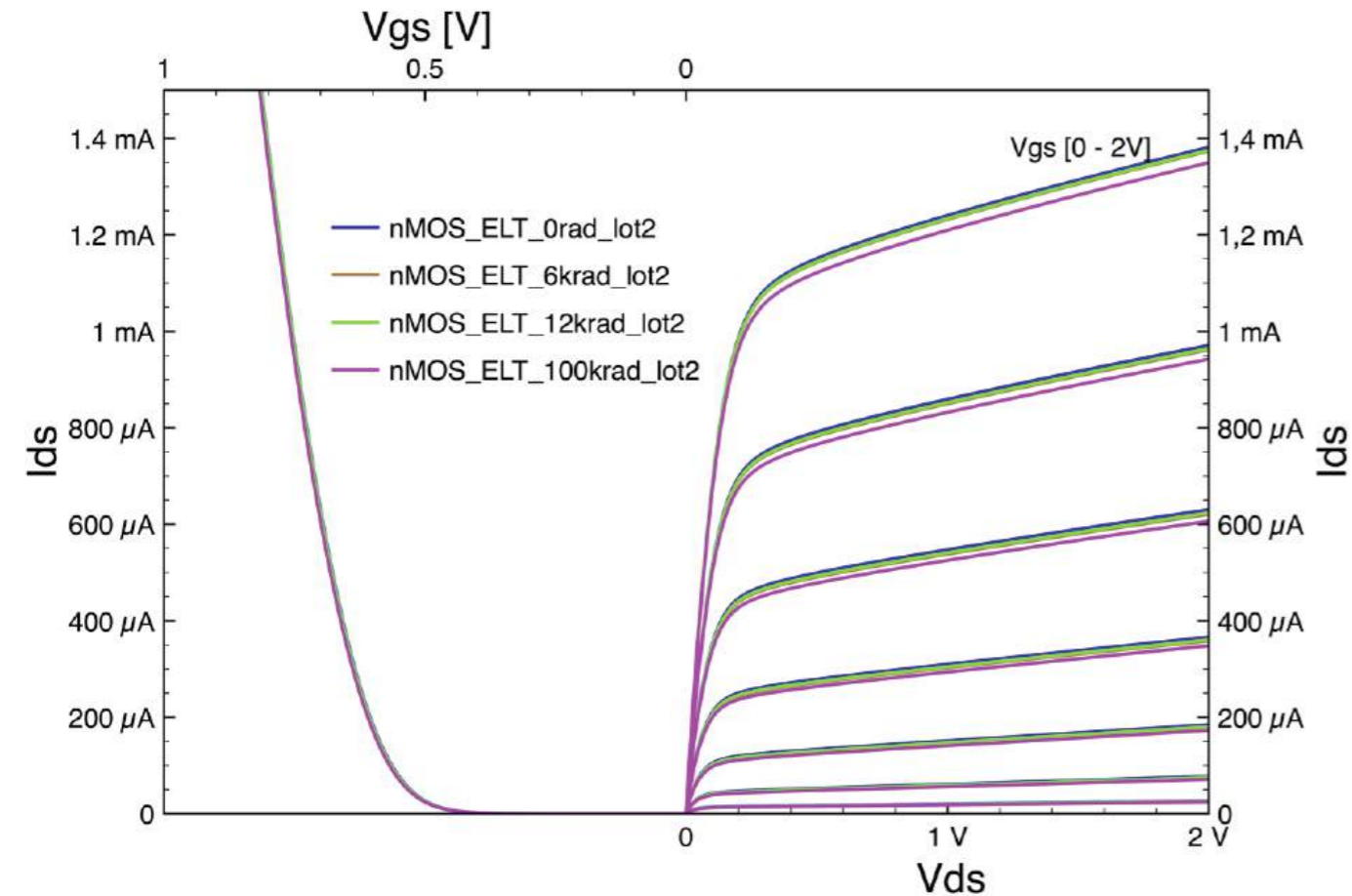
- TID (Total Ionizing Dose): **accumulative** effect
- γ source Cobalt 60 with 1.25 MeV, COCASE, CEA-Saclay, >1 months
- 1.4–7 krad during the 5 years lifetime of ATHENA at L2 point

Pack 1	0 rad	1.7 krad	6 krad	8 krad	10 krad
Pack 2	0 krad	6 krad	12 krad	100 krad	

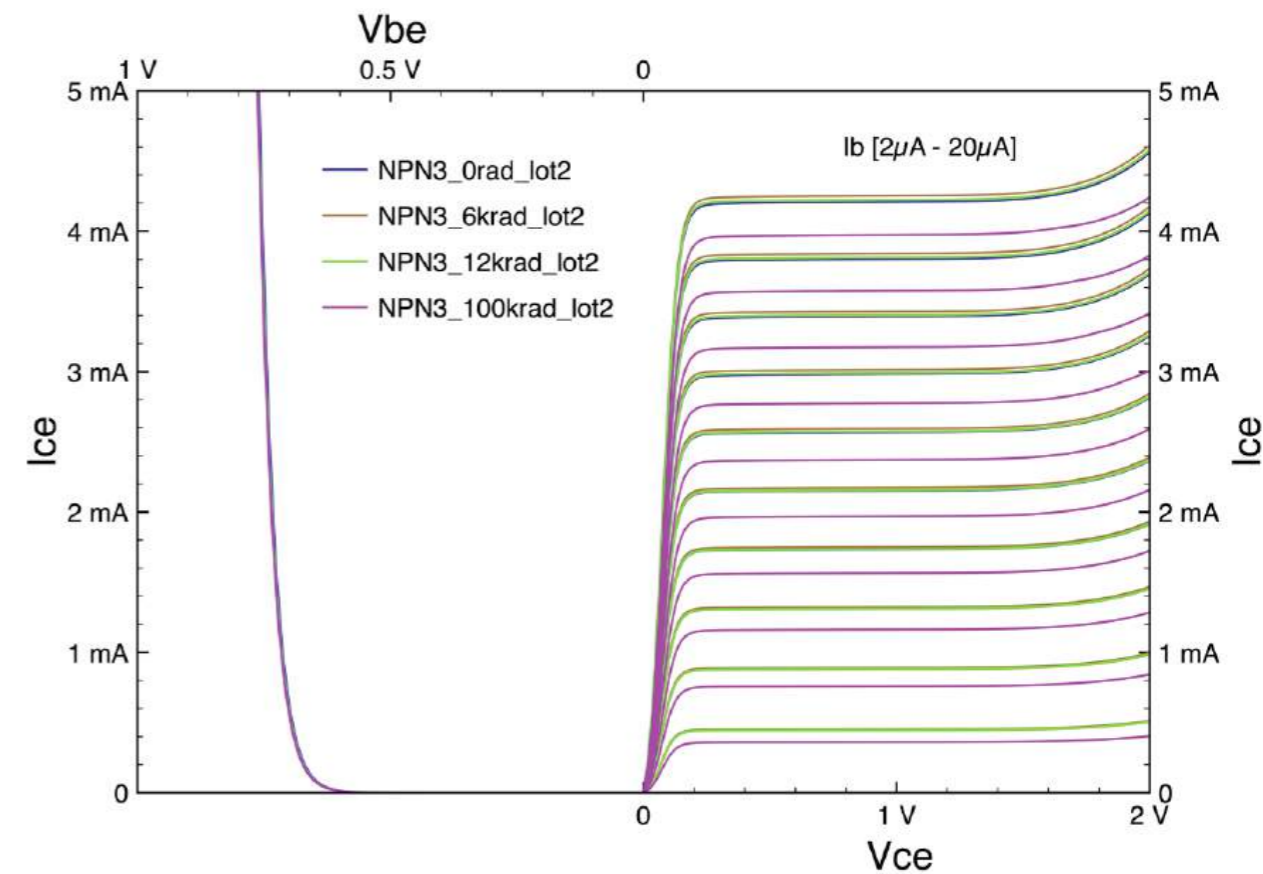
- Positive charged particles trapped in oxide may cause a noticeable leakage current between drain and source, thus change the DC characteristics of MOS



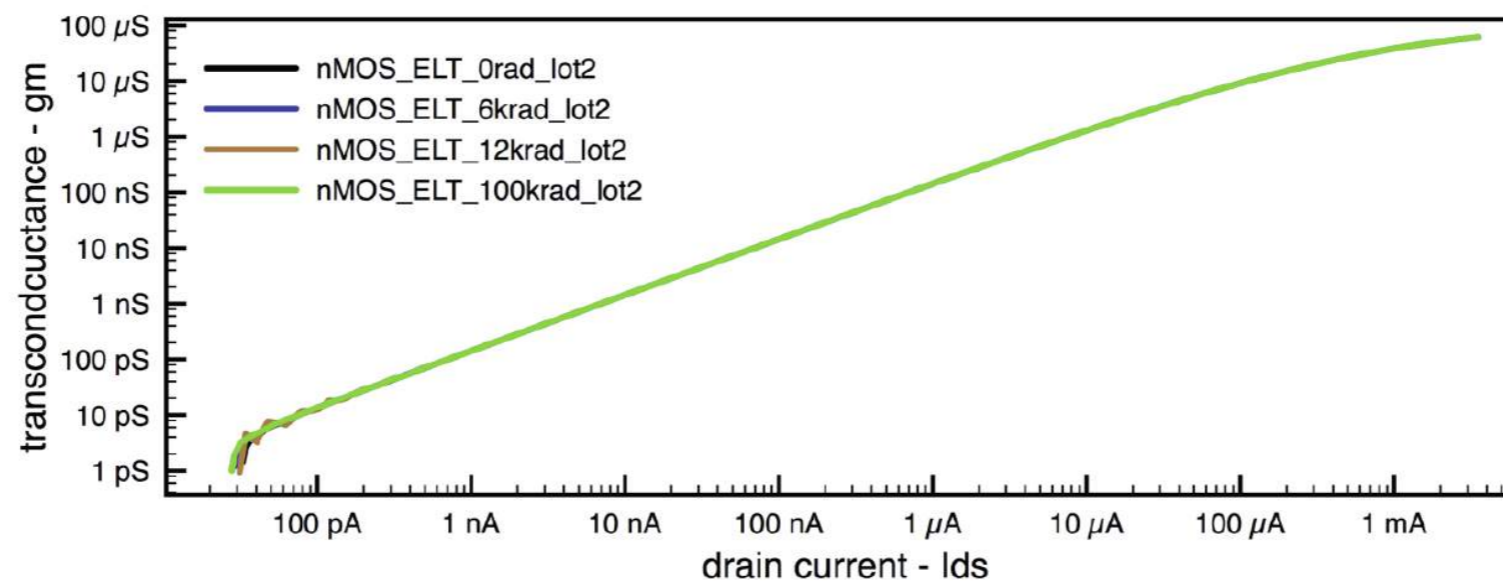
NMOS ELT $I_{ds}(V_{gs})$ & $I_{ds}(V_{ds})$



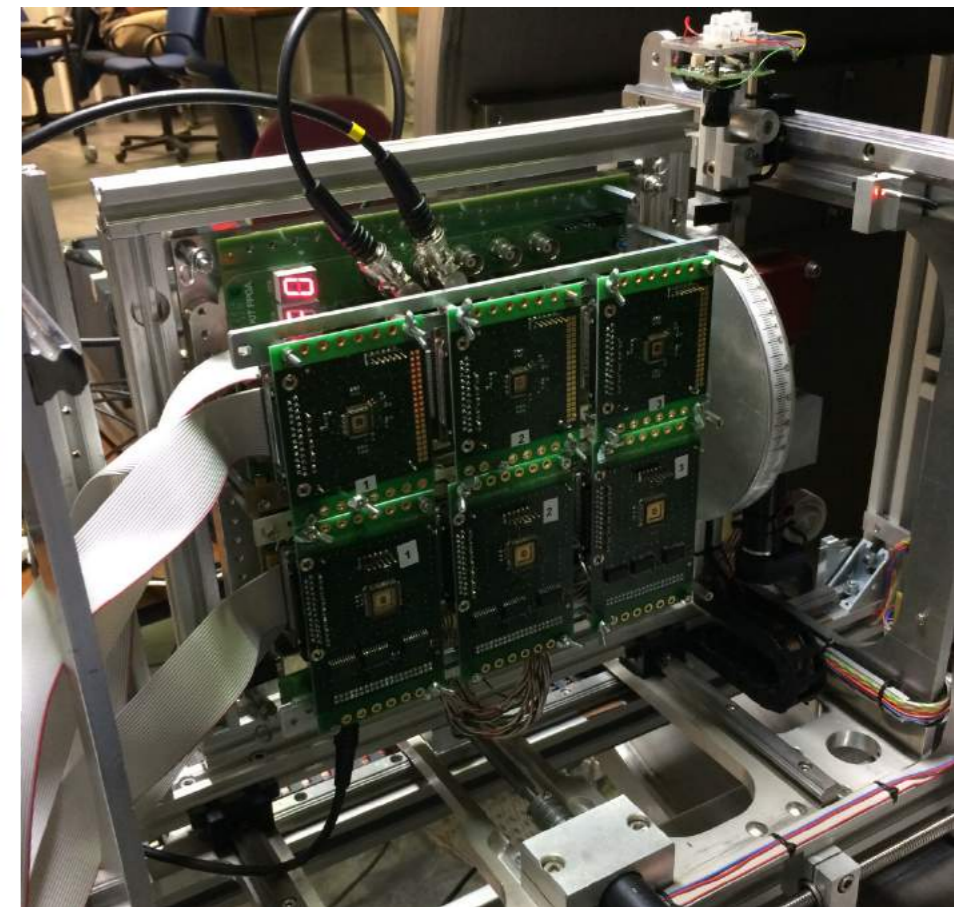
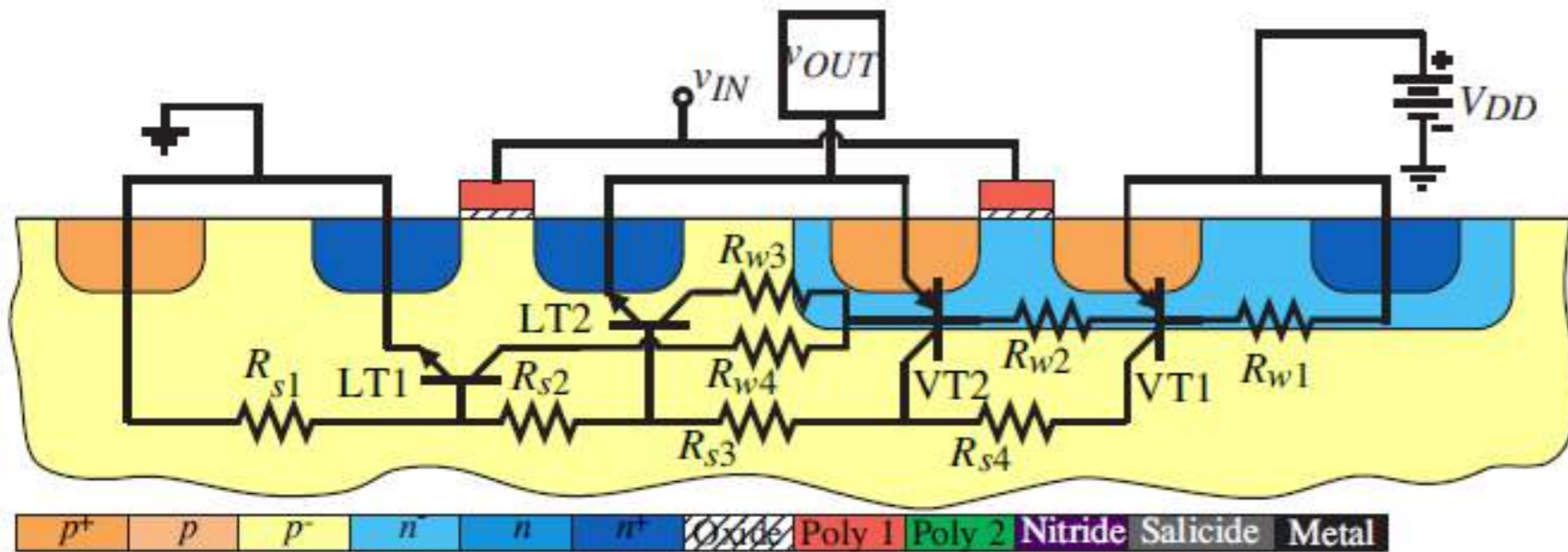
nnp BJT $I_{ce}(V_{be})$ & $I_{ce}(V_{ce})$



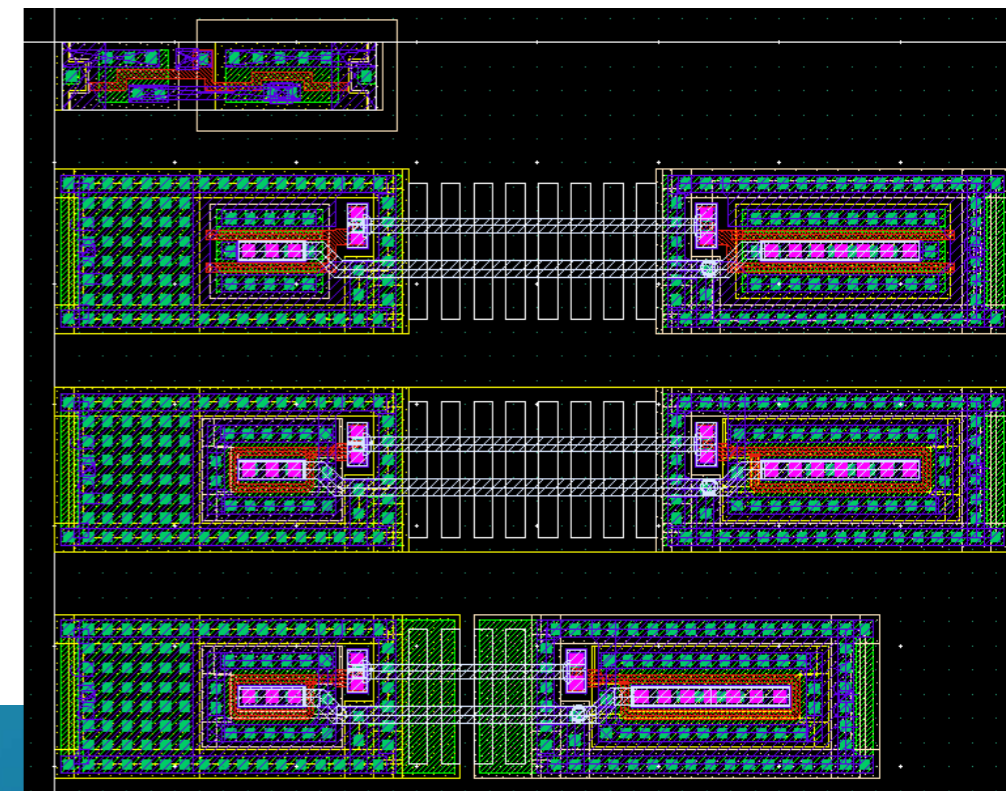
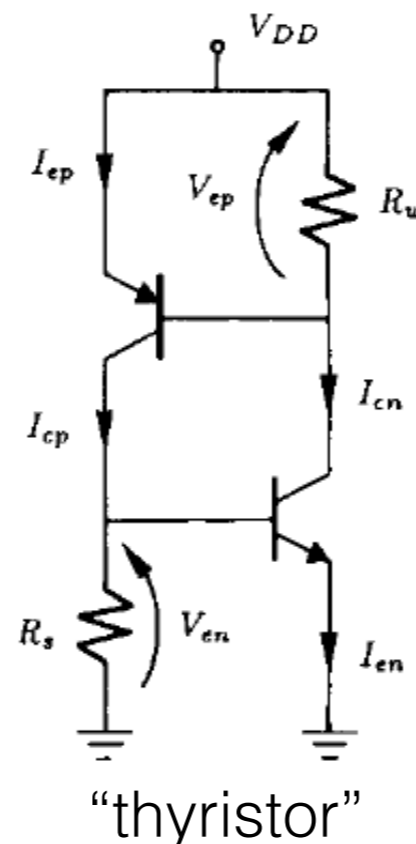
NMOS ELT transconductance $g_m = dI_{ds}/dV_{gs}$



SEL (Single Event Latch-up): caused by heavy ions or protons from cosmic rays or solar flares

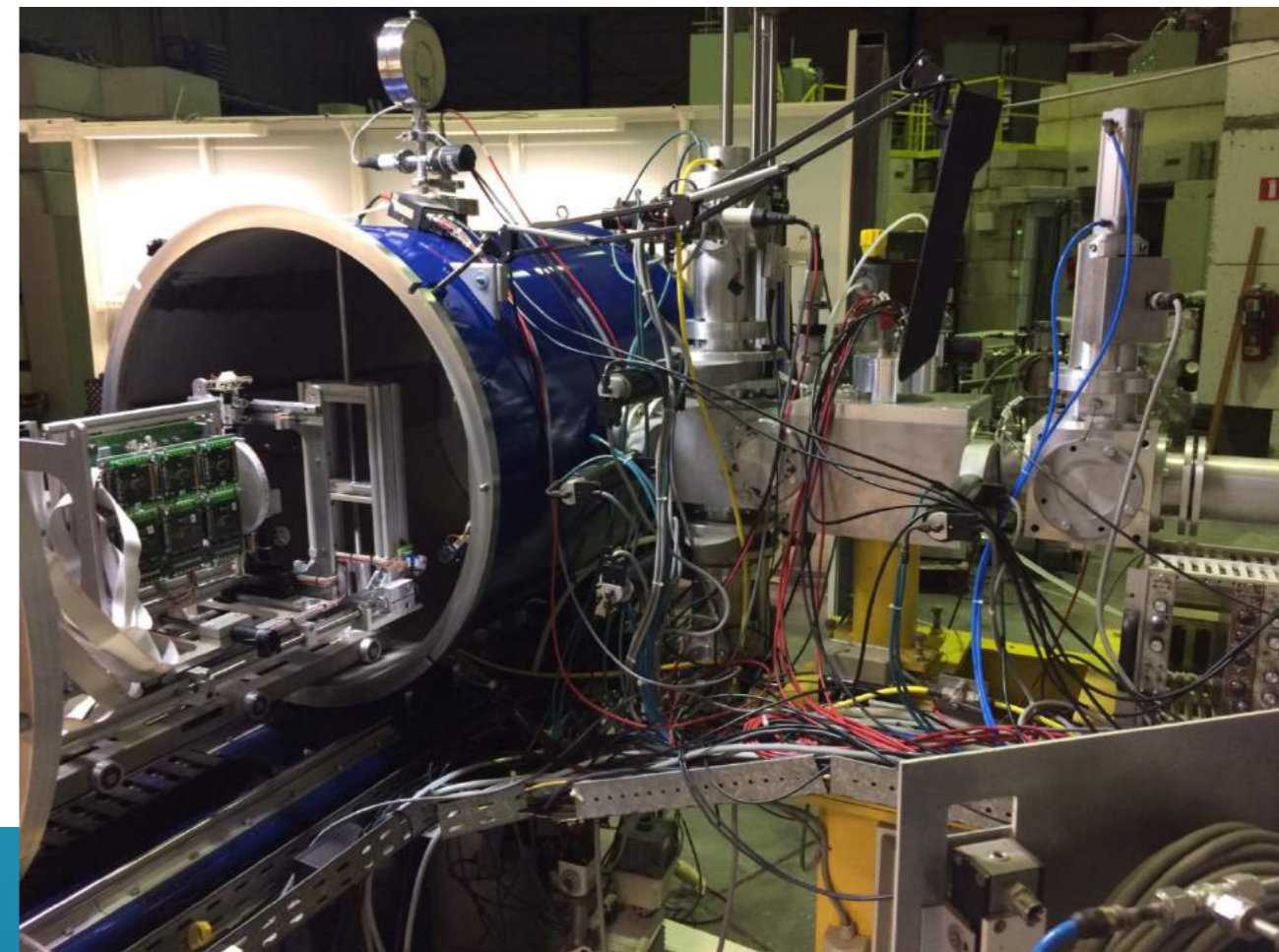
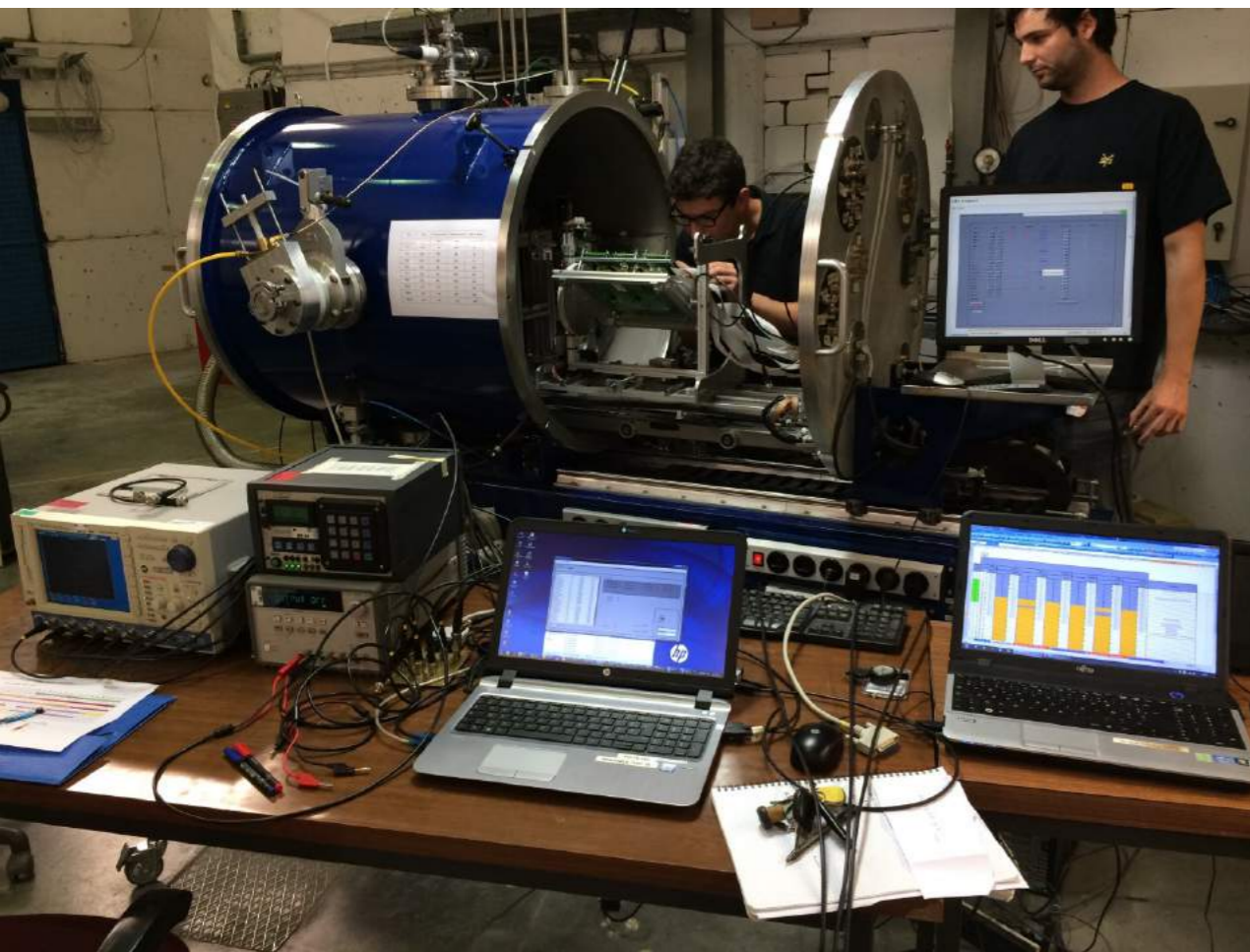


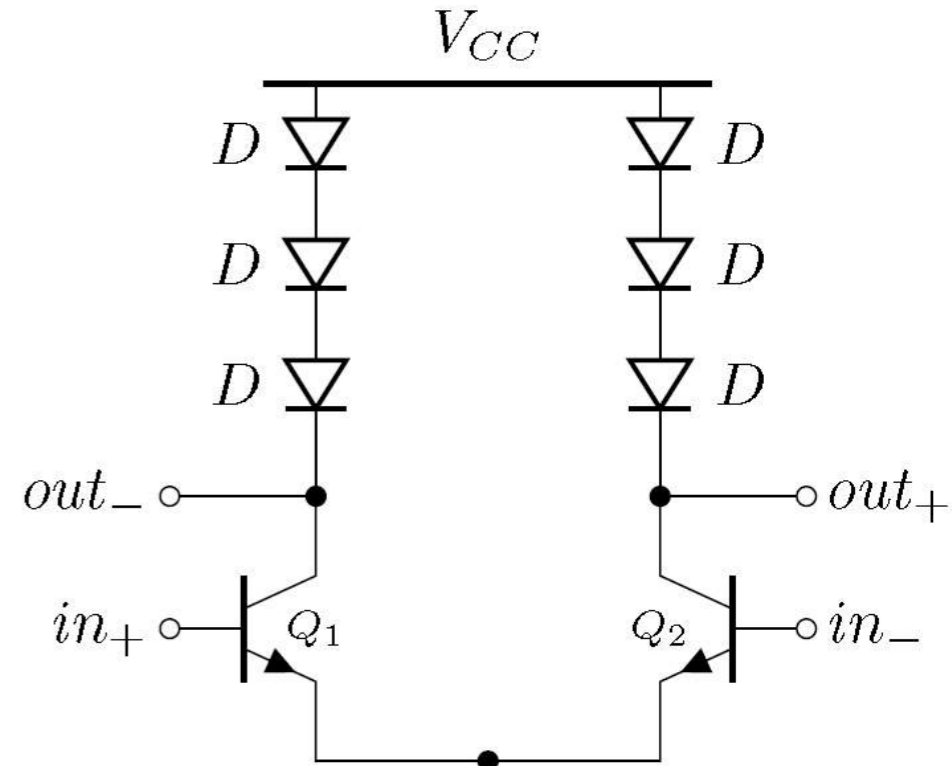
"Cause I'm the one who's gonna make you **burn**"



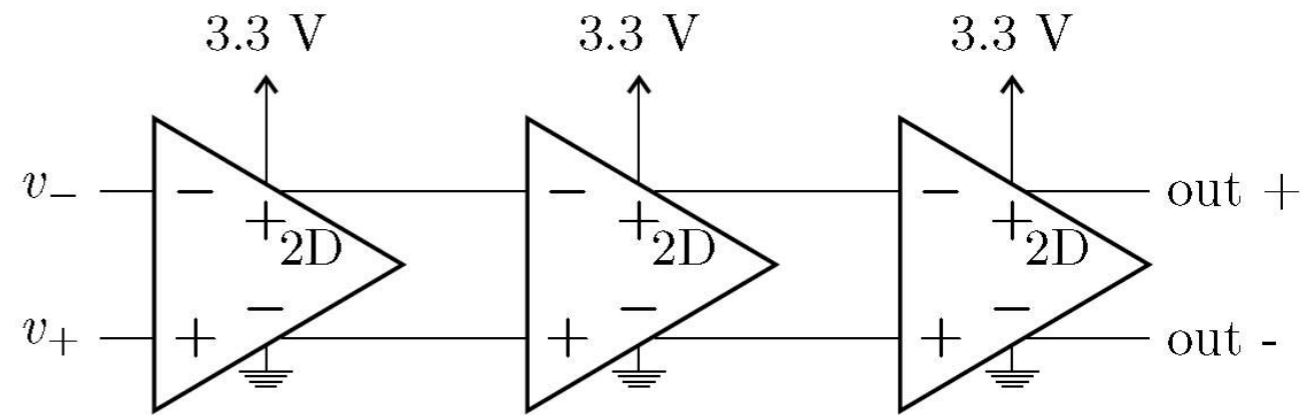
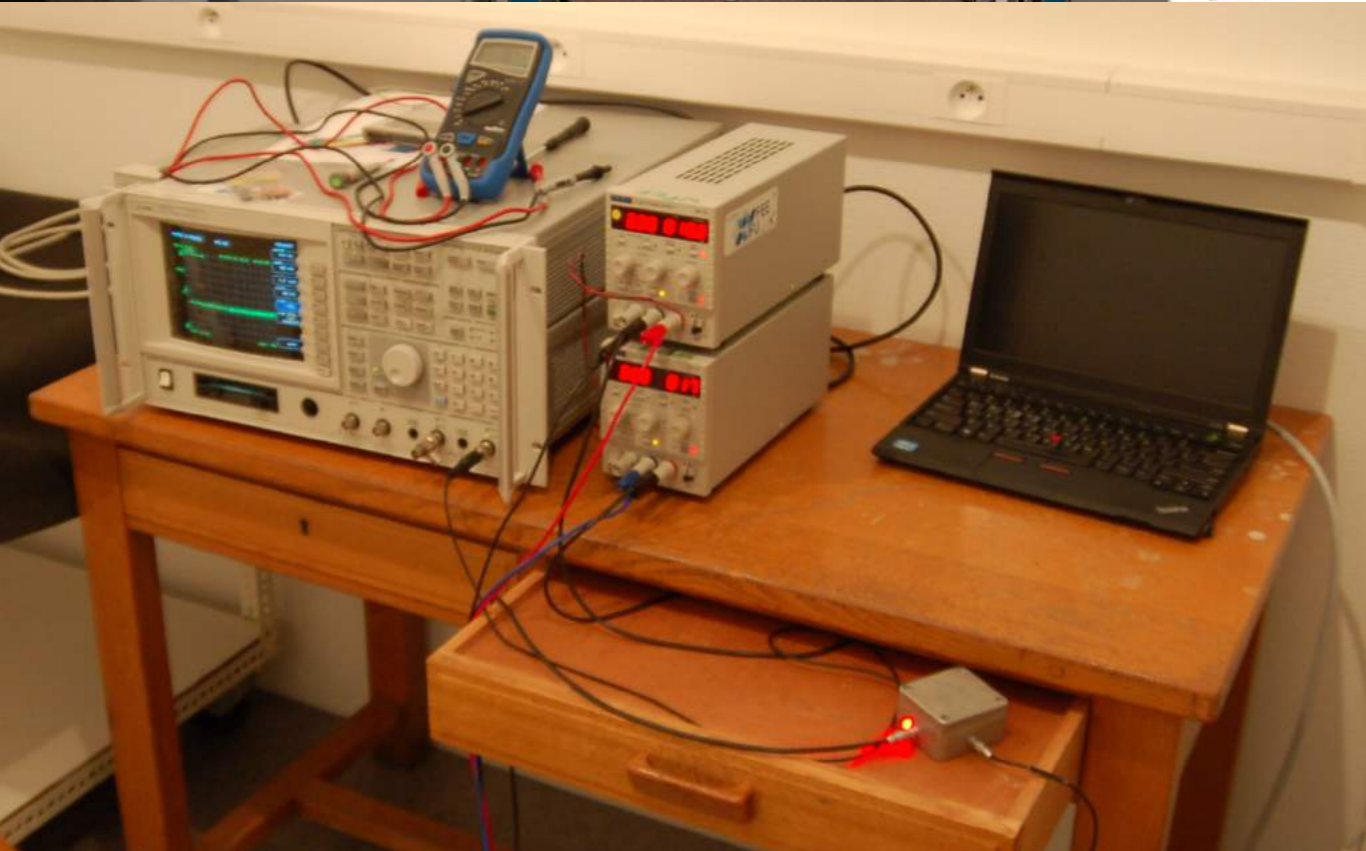
❖ Cyclotron, Universite Catholique de Louvain, Belgium

Ion	M/Q	DUT energy [Mev]	Range [$\mu\text{m Si}$]	LET [MeV/mg/cm^2]
Carbon $^{13}\text{C}^{4+}$	3.25	131	269.3	1.3
Neon $^{22}\text{Ne}^{7+}$	3.14	238	202.0	3.3
Aluminium $^{27}\text{Al}^{8+}$	3.37	250	131.2	5.7
Argon $^{40}\text{Ar}^{12+}$	3.33	379	120.5	10.0
Chromium $^{53}\text{Cr}^{16+}$	3.31	513	107.6	16.0
Nickel $^{58}\text{Ni}^{18+}$	3.218	582	100.5	20.4
Krypton $^{84}\text{Kr}^{25+}$	3.35	769	94.2	32.4
Rhodium $^{103}\text{Rh}^{31+}$	3.32	972	88.7	45.8
Xenon $^{124}\text{Xe}^{35+}$	3.54	995	73.1	62.5





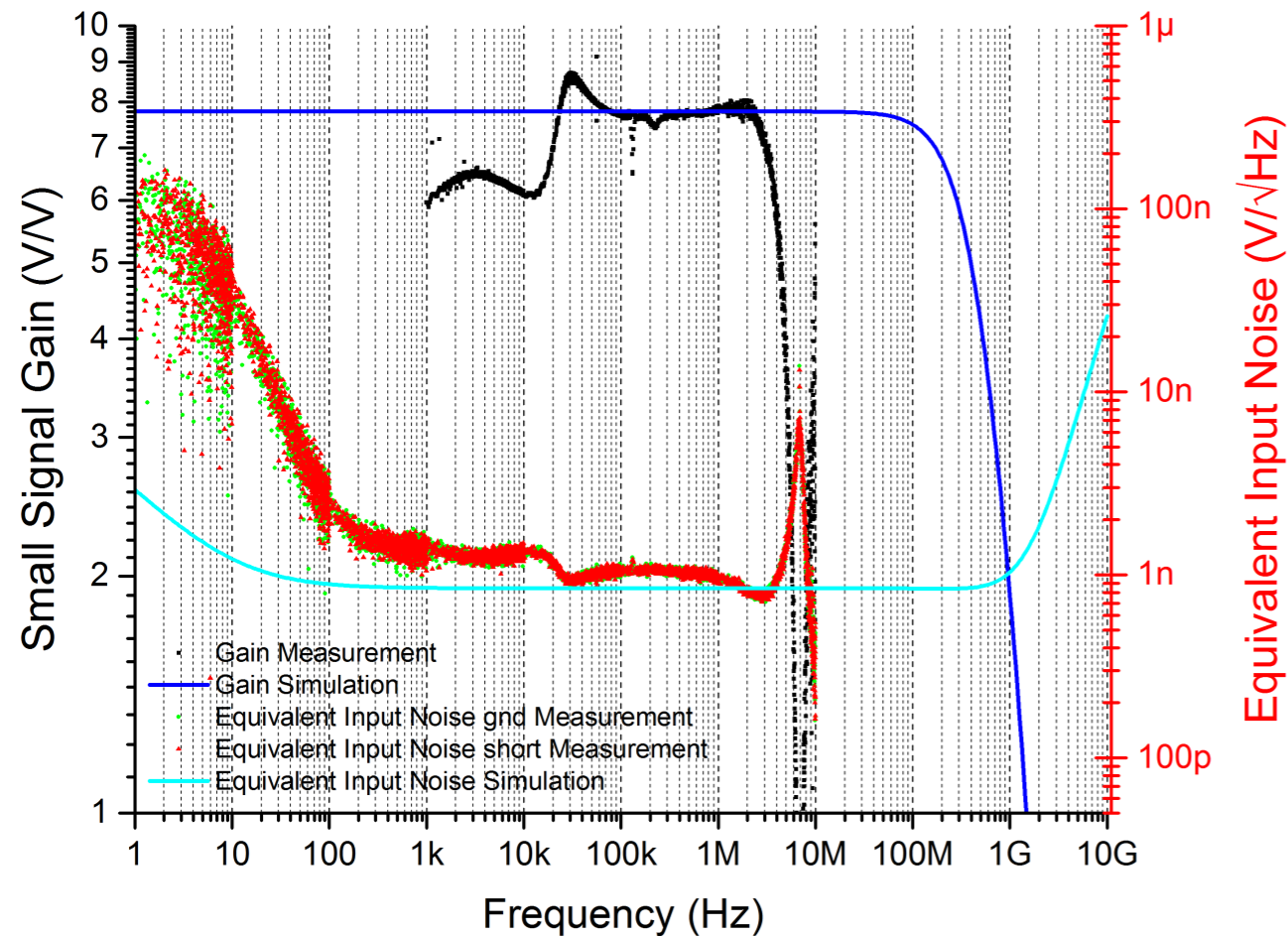
$$\begin{aligned}
 |Gain| &= g_m \times Z_d \times n_d \\
 &= \frac{qI_c}{kT} \times \frac{kT}{qI_d} \times n_d \\
 &= n_d
 \end{aligned}
 \quad \text{Gain} = 3$$



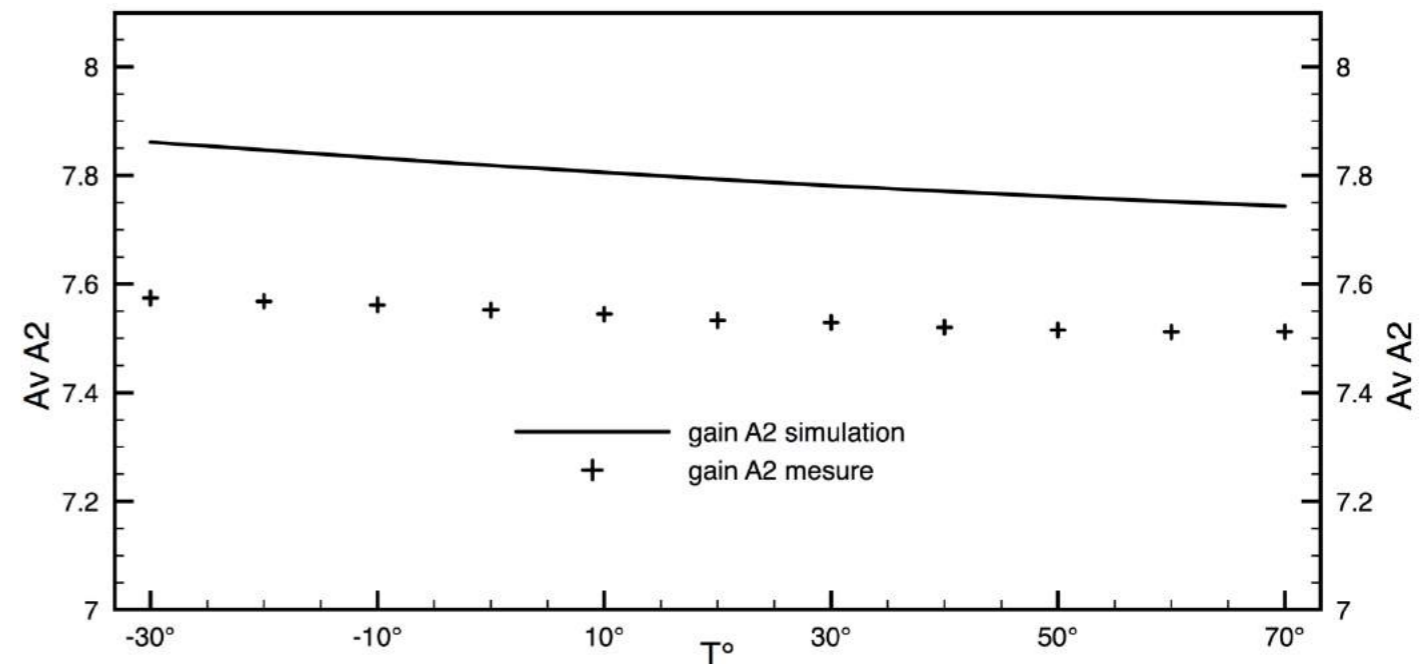
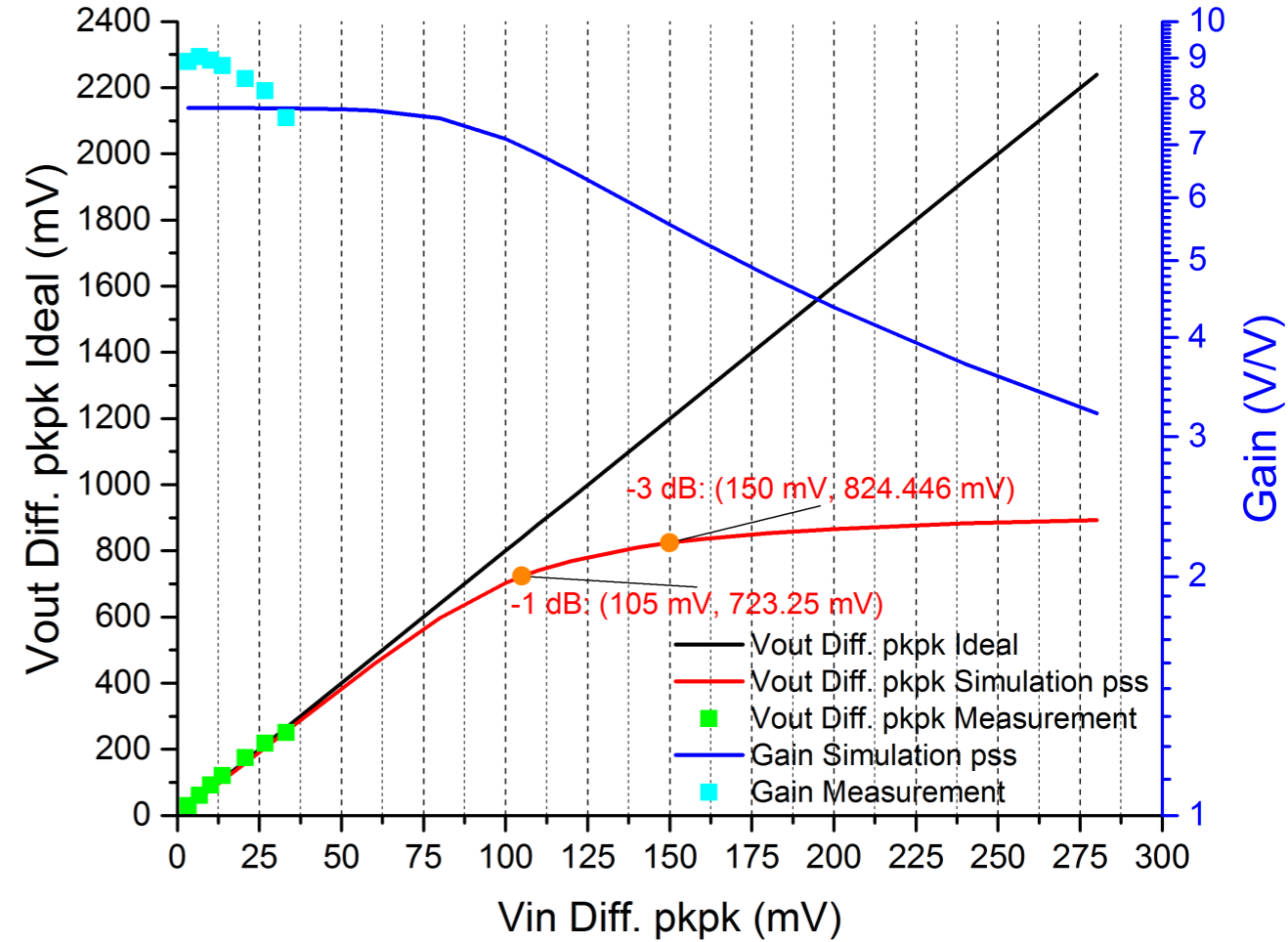
$$\text{Gain} = 2 * 2 * 2 = 8$$

- ✈ Gain ≈ 8
- ✈ Noise $\approx 1 \text{ nV}/\sqrt{\text{Hz}}$

Small Signal Gain and Equivalent Input Noise
Measurement and Simulation for LNA A2



Gain Linearity - 6 MHz
Measurement and Simulation for LNA A2





WFEE identified Specifications



	Identified spec	ASICv1 measure	ASICv2 goal
Gain	80 V/V	3, 8, 24 V/V	
Noise	1 nV/ \sqrt{Hz}	≈ 1 nV/ \sqrt{Hz}	
BW	1-6 MHz	DC-10 MHz*	
Linearity	1% on 1 Vpp	1% on 0.2 Vpp	
Drift	17 μ V/V x10	≈ 200 ppm/K	
Serial link	RS 485	I2C	
TID	1.7 - 14 krad	100 krad	
LET	10 MeV/mg/cm ²	120 MeV/mg/cm ²	

* Small signal



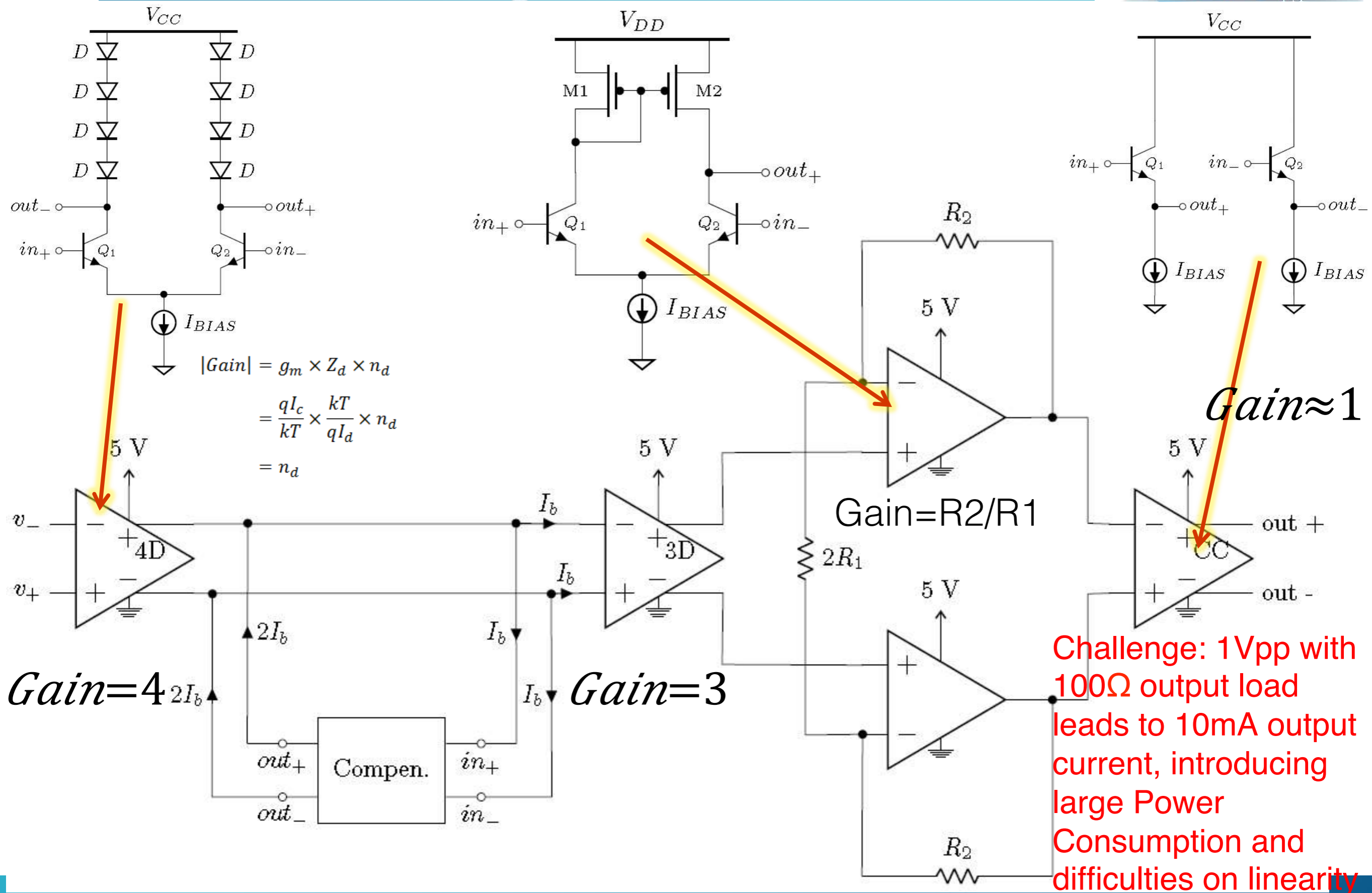
WFEE identified Specifications



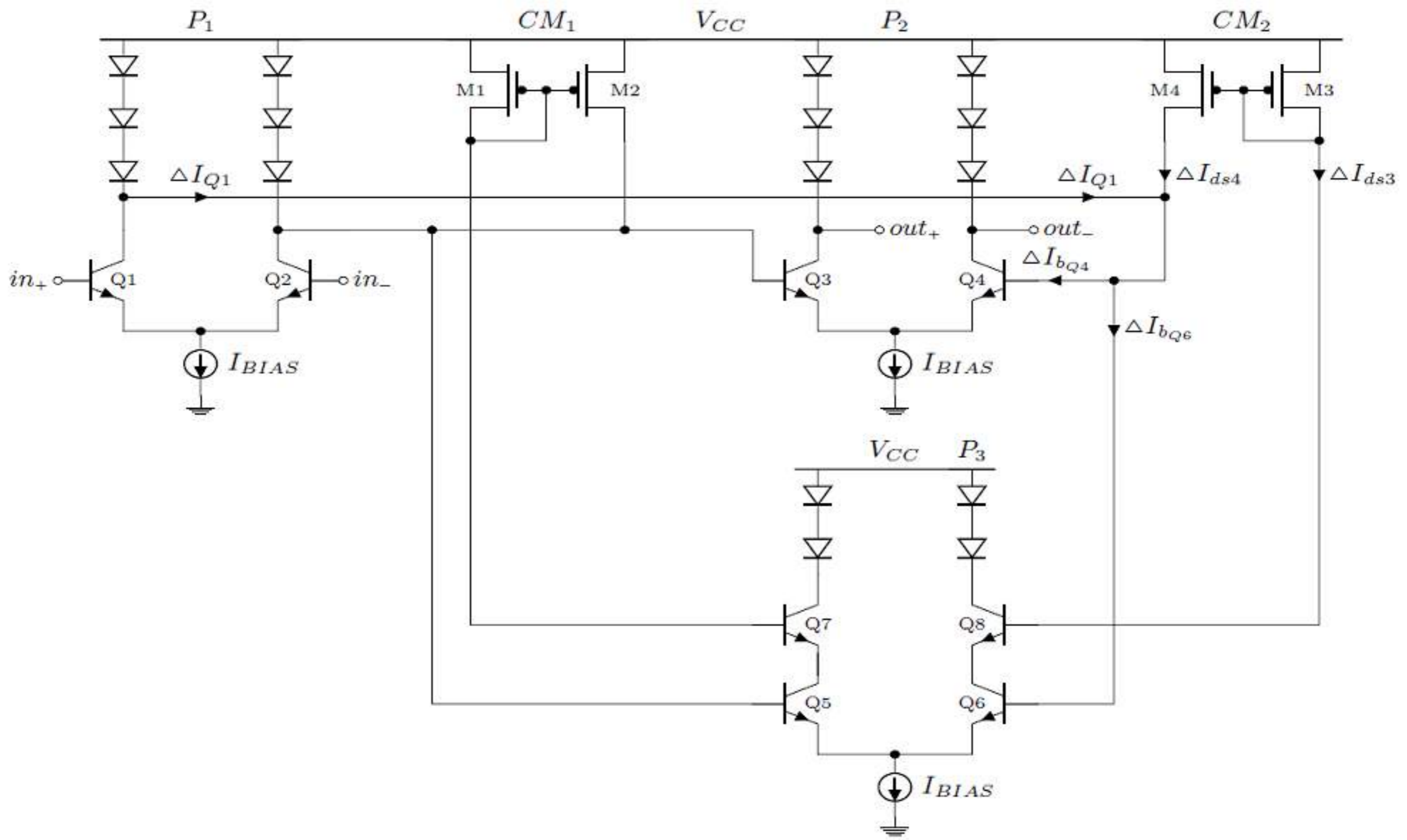
	Identified spec	ASICv1 measure	ASICv2 goal
Gain	80 V/V	3, 8, 24 V/V	80 V/V
Noise	1 nV/ \sqrt{Hz}	≈ 1 nV/ \sqrt{Hz}	< 1 nV/ \sqrt{Hz}
BW	1-6 MHz	DC-10 MHz*	DC-6 MHz**
Linearity	1% on 1 Vpp	1% on 0.2 Vpp	1% on 1 Vpp
Drift	17 μ V/V x10	≈ 200 ppm/K	< 300 ppm/K
Serial link	RS 485	I2C	I2C _{in} /RS485 _{out}
TID	1.7 - 14 krad	100 krad	-
LET	10 MeV/mg/cm ²	120 MeV/mg/cm ²	-

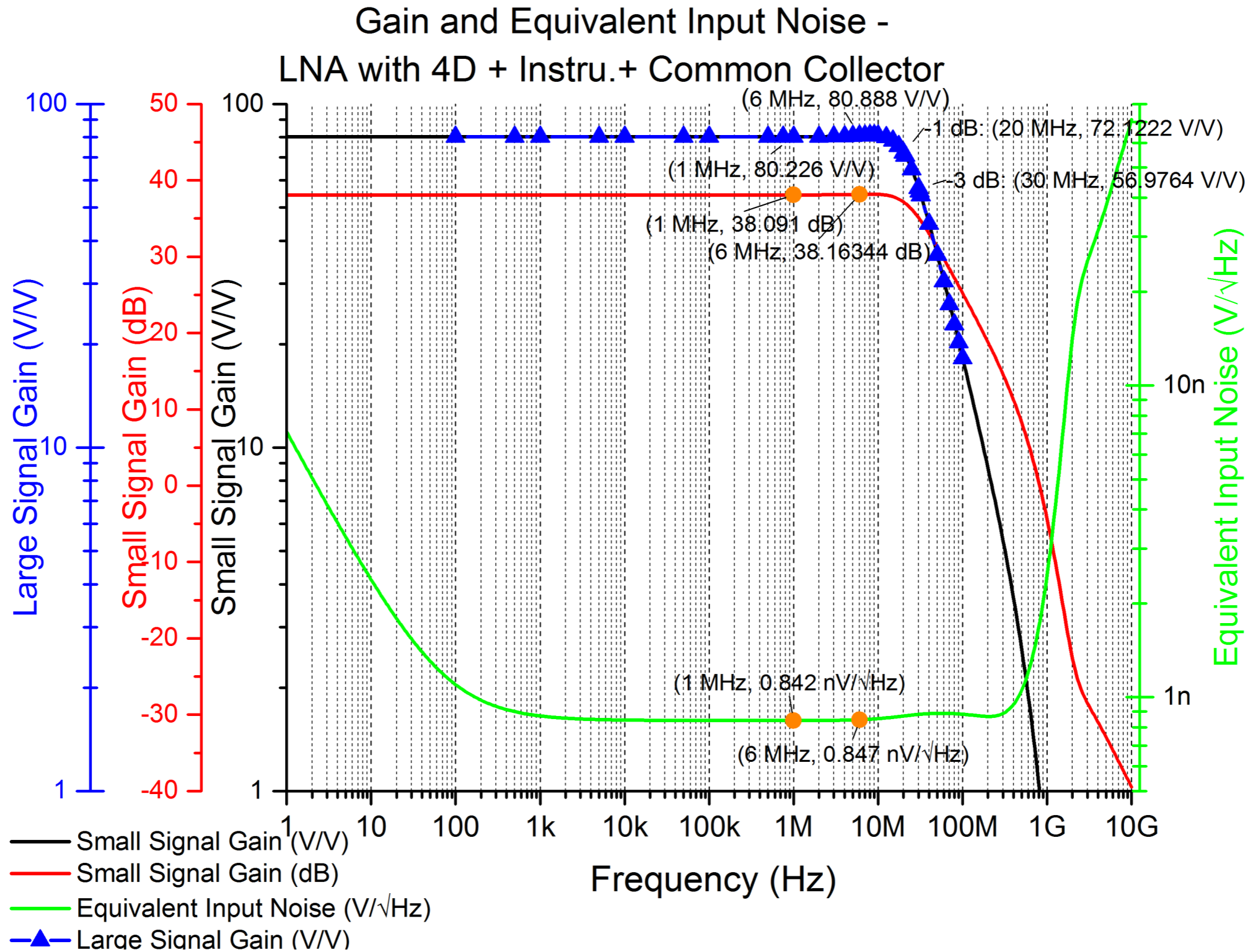
* Small signal

** Small and full dynamic (slew rate)

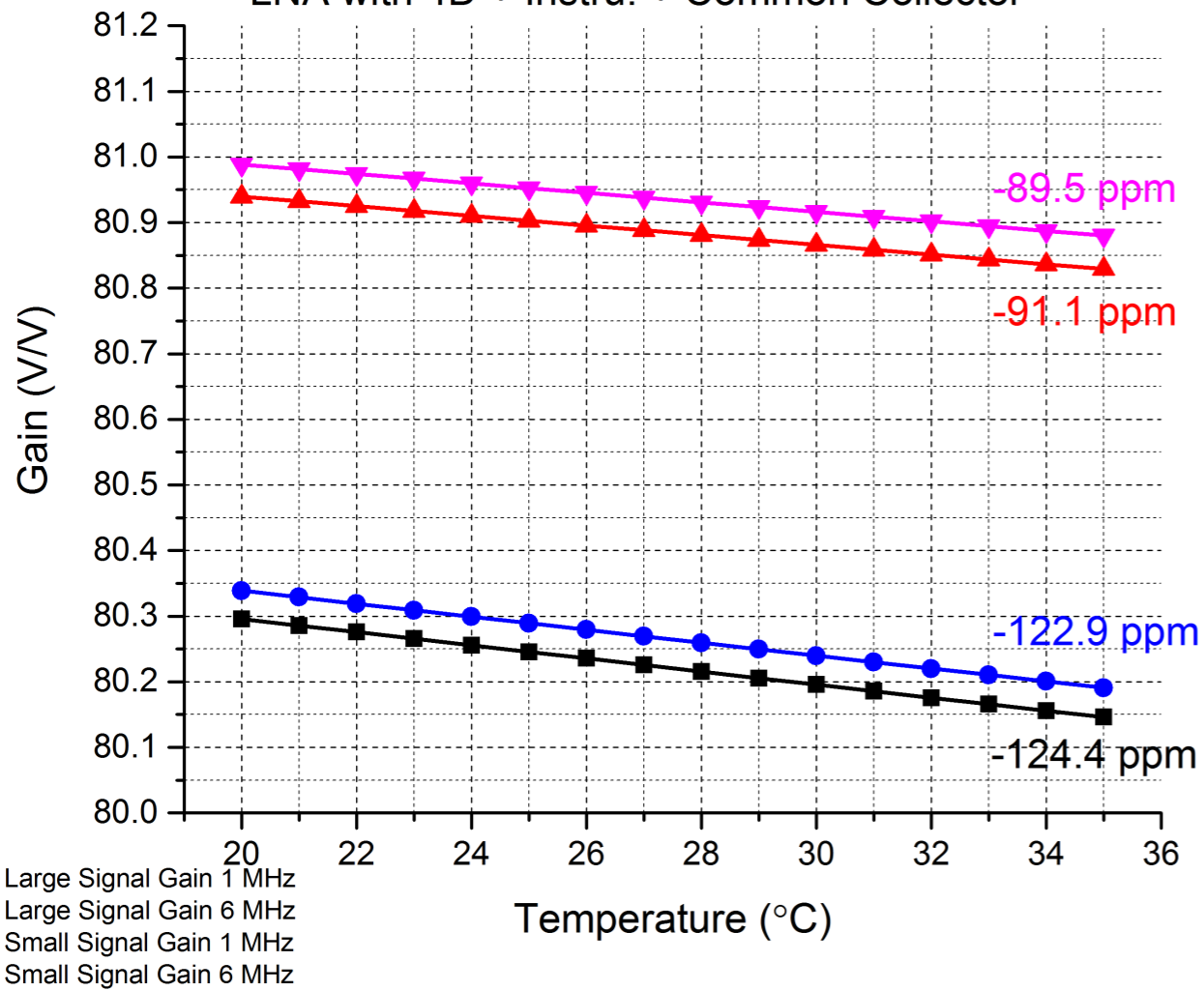


Compensation system of Base current of npn bipolar transistor

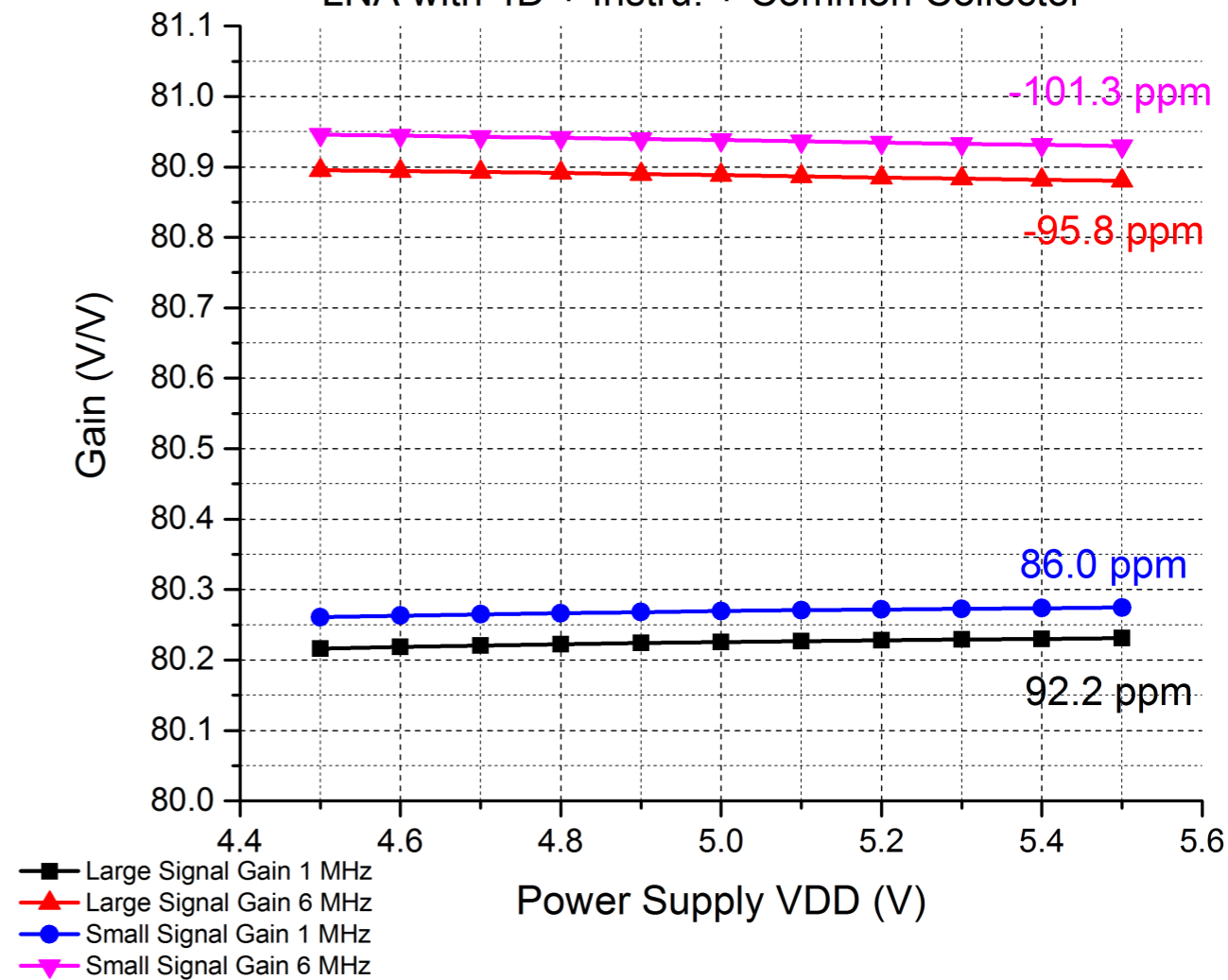


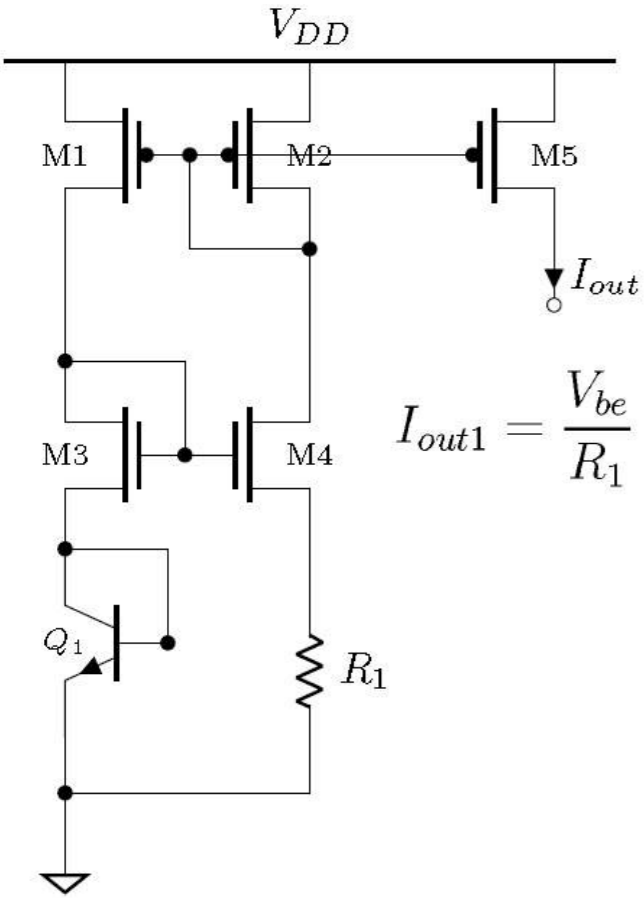


Gain Stability - Gain vs. Temperature
LNA with 4D + Instru. + Common Collector



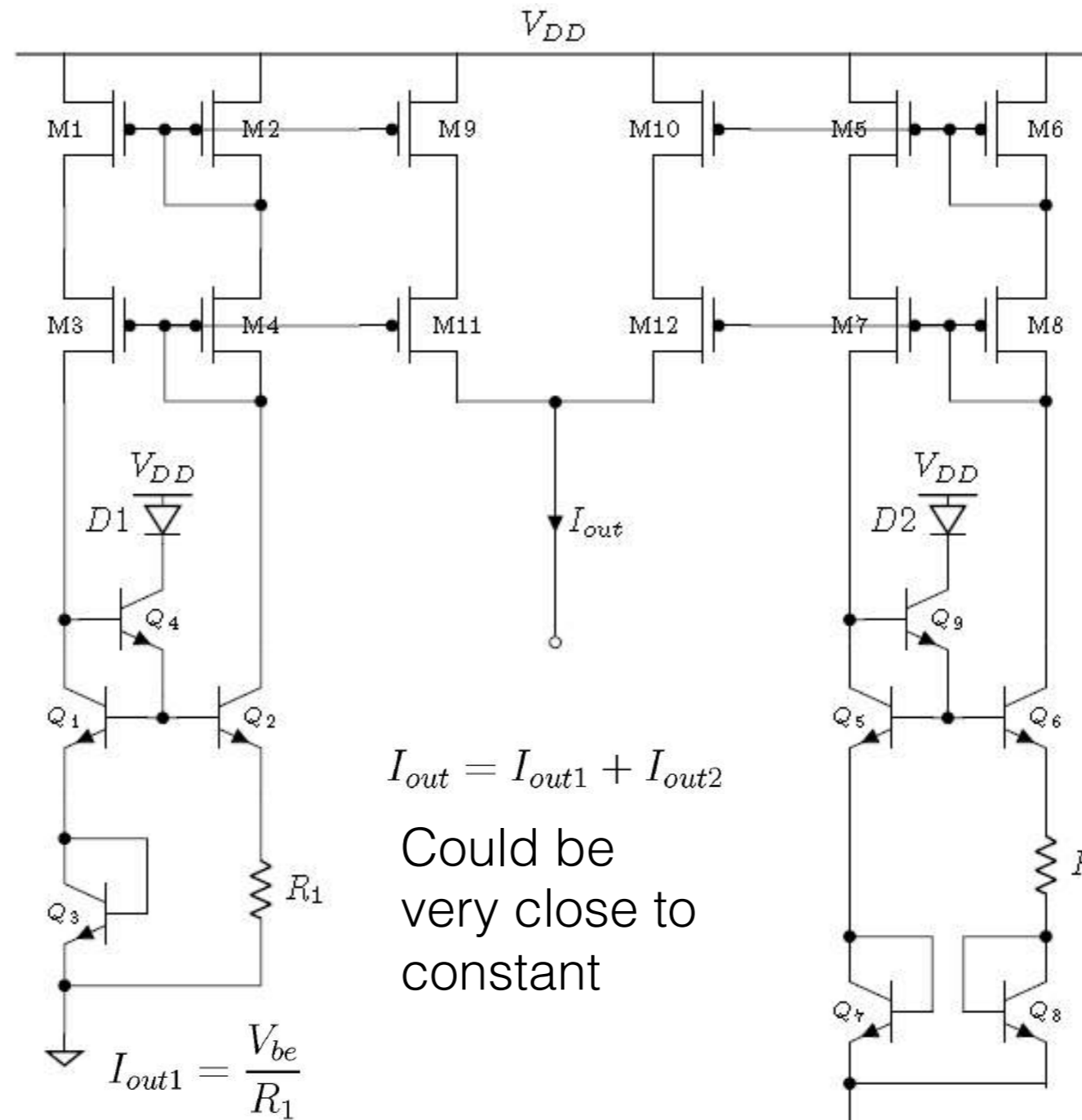
Gain Stability - Gain vs. Power Supply VDD
LNA with 4D + Instru. + Common Collector





$$I_{out1} = \frac{V_{be}}{R_1}$$

Negative temperature coefficient



$$I_{out} = I_{out1} + I_{out2}$$

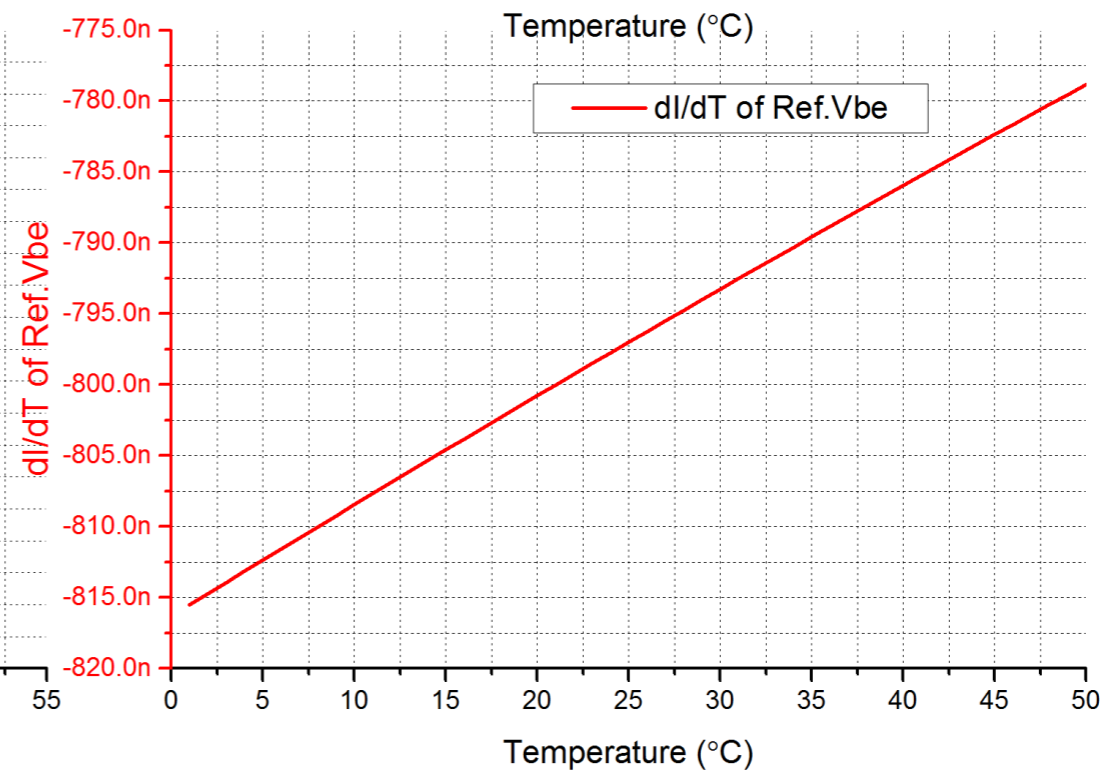
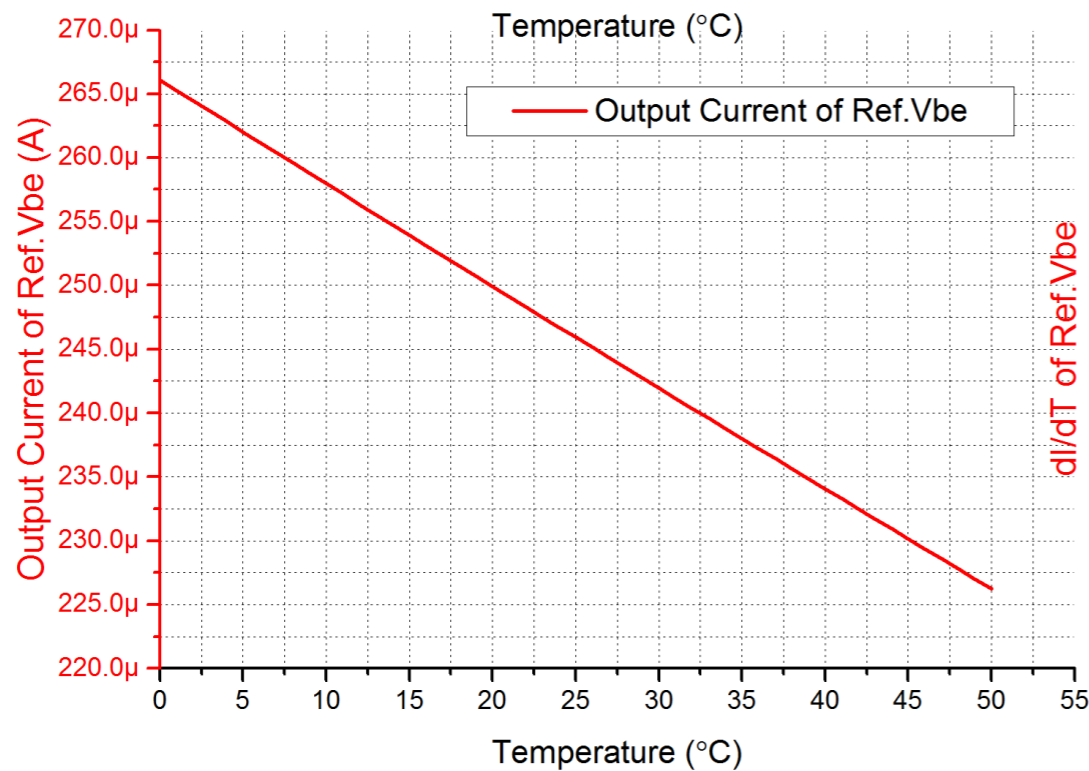
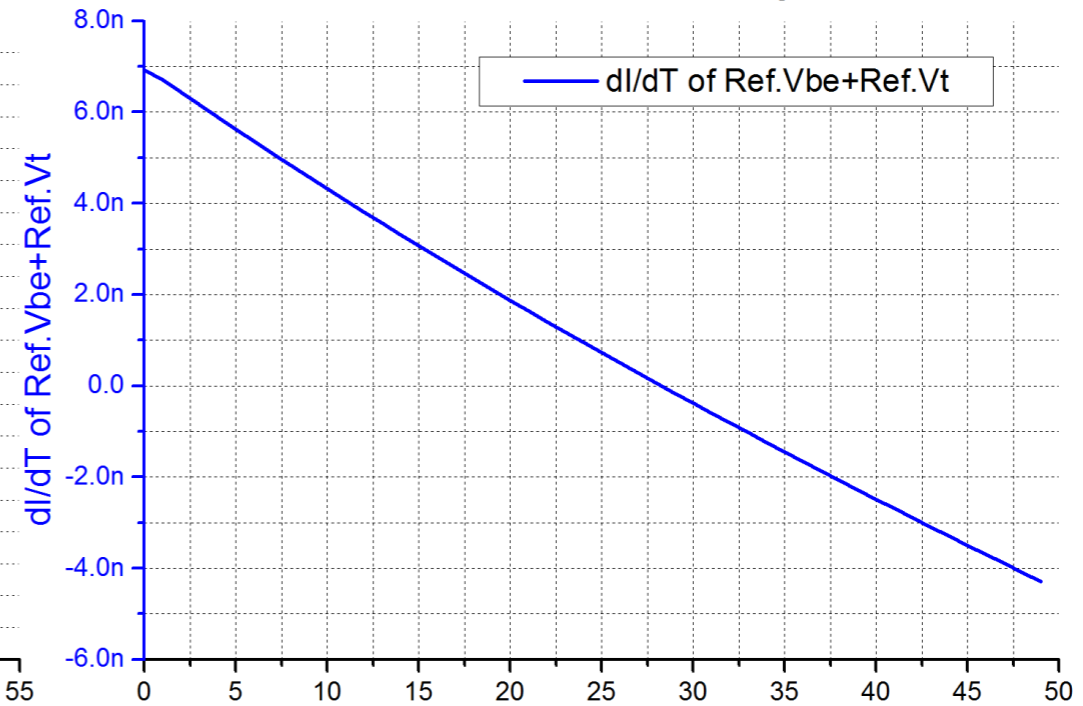
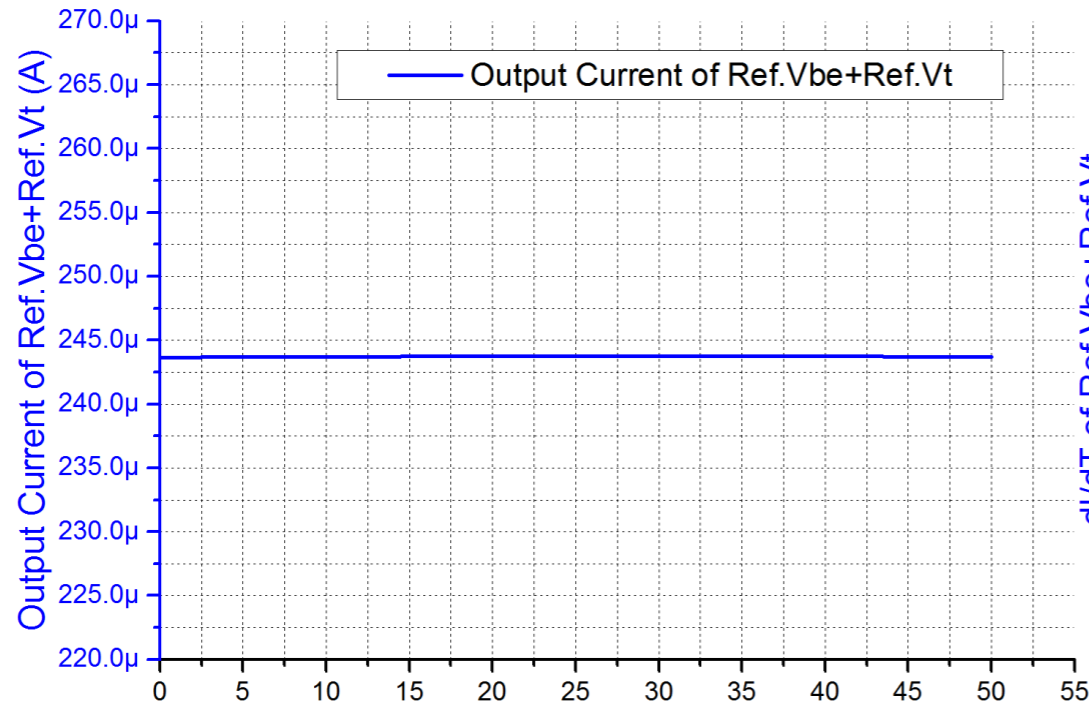
Could be very close to constant

Negative temperature coefficient

Positive temperature coefficient

$$\begin{aligned} I_{out2} &= \frac{\Delta V_{be}}{R_2} = \frac{V_{be7} - V_{be8}}{R_2} \\ &= \frac{V_T \ln \frac{I_0}{I_s} - V_T \ln \frac{I_0}{m I_s}}{R_2} \\ &= \frac{V_T \ln m}{R_2} \end{aligned}$$

Output Current vs. Temperature for Current Source with Ref.Vt+Ref.Vbe and Current Source only with Ref.Vbe



✦ Simulations, Layout, Post-simulation (before 03/2018)

✦ Measurements (07/2018 -)

	Identified spec	ASICv1 measure	ASICv2 goal
Gain	80 V/V	3, 8, 24 V/V	80 V/V
Noise	1 nV/ \sqrt{Hz}	≈ 1 nV/ \sqrt{Hz}	< 1 nV/ \sqrt{Hz}
BW	1-6 MHz	DC-10 MHz*	DC-6 MHz**
Linearity	1% on 1 Vpp	1% on 0.2 Vpp	1% on 1 Vpp
Drift	17 μ V/V x10	≈ 200 ppm/K	< 300 ppm/K
Serial link	RS 485	I2C	I2C _{in} /RS485 _{out}
TID	1.7 - 14 krad	100 krad	-
LET	10 MeV/mg/cm ²	120 MeV/mg/cm ²	-

* Small signal

** Small and full dynamic (slew rate)

Merci!

A close-up photograph of a white fountain pen with a blue ring, writing the word 'Merci!' in elegant cursive on a white surface.

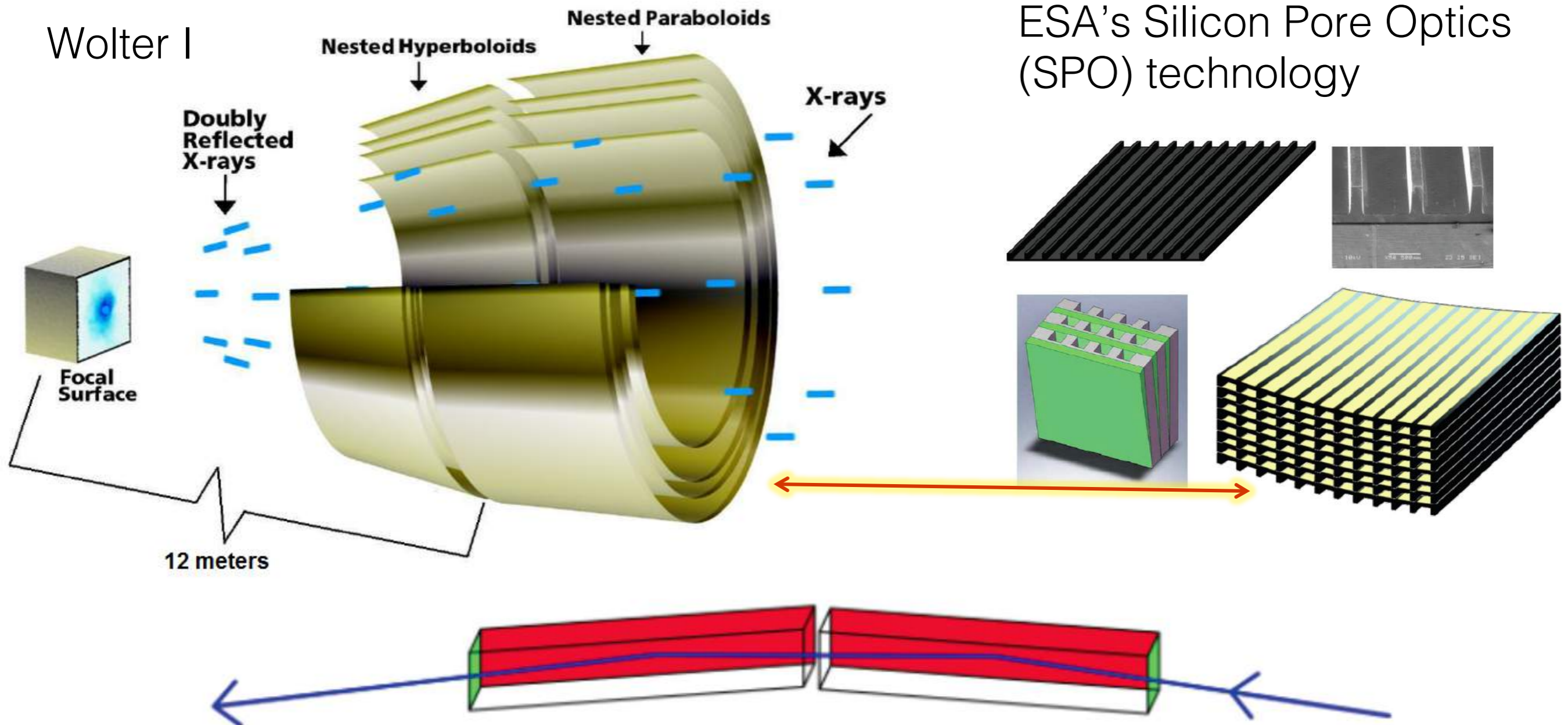
Key parameters and requirements of the Athena+ mission

Parameter	Requirements	Enabling technology/comments
Effective Area	2 m ² @ 1 keV (goal 2.5 m ²) 0.25 m ² @ 6 keV (goal 0.3 m ²)	Silicon Pore Optics developed by ESA. Single telescope: 3 m outer diameter, 12 m fixed focal length.
Angular Resolution	5" (goal 3") on-axis 10" at 25' radius	<i>Detailed analysis of error budget confirms that a performance of 5" HEW is feasible.</i>
Energy Range	0.3-12 keV	Grazing incidence optics & detectors.
Instrument Field of View	<i>Wide-Field Imager: (WFI): 40' (goal 50')</i>	Large area DEPFET Active Pixel Sensors.
	<i>X-ray Integral Field Unit: (X-IFU): 5' (goal 7')</i>	Large array of multiplexed Transition Edge Sensors (TES) with 250 micron pixels.
Spectral Resolution	WFI: <150 eV @ 6 keV	Large area DEPFET Active Pixel Sensors.
	X-IFU: 2.5 eV @ 6 keV (goal 1.5 eV @ 1 keV)	<i>Inner array (10"x10") optimized for goal resolution at low energy (50 micron pixels).</i>
Count Rate Capability	> 1 Crab ¹ (WFI)	<i>Central chip for high count rates without pile-up and with micro-second time resolution.</i>
	1 mCrab, point source (X-IFU) with 90% of high-resolution events	<i>Filters and beam diffuser enable higher count rate capability with reduced spectral resolution.</i>
Target of Opportunity Response	4 hours (goal 2 hours) for 50% of time	<i>Slew times <2 hours feasible; total response time dependent on ground system issues.</i>

3 key components:

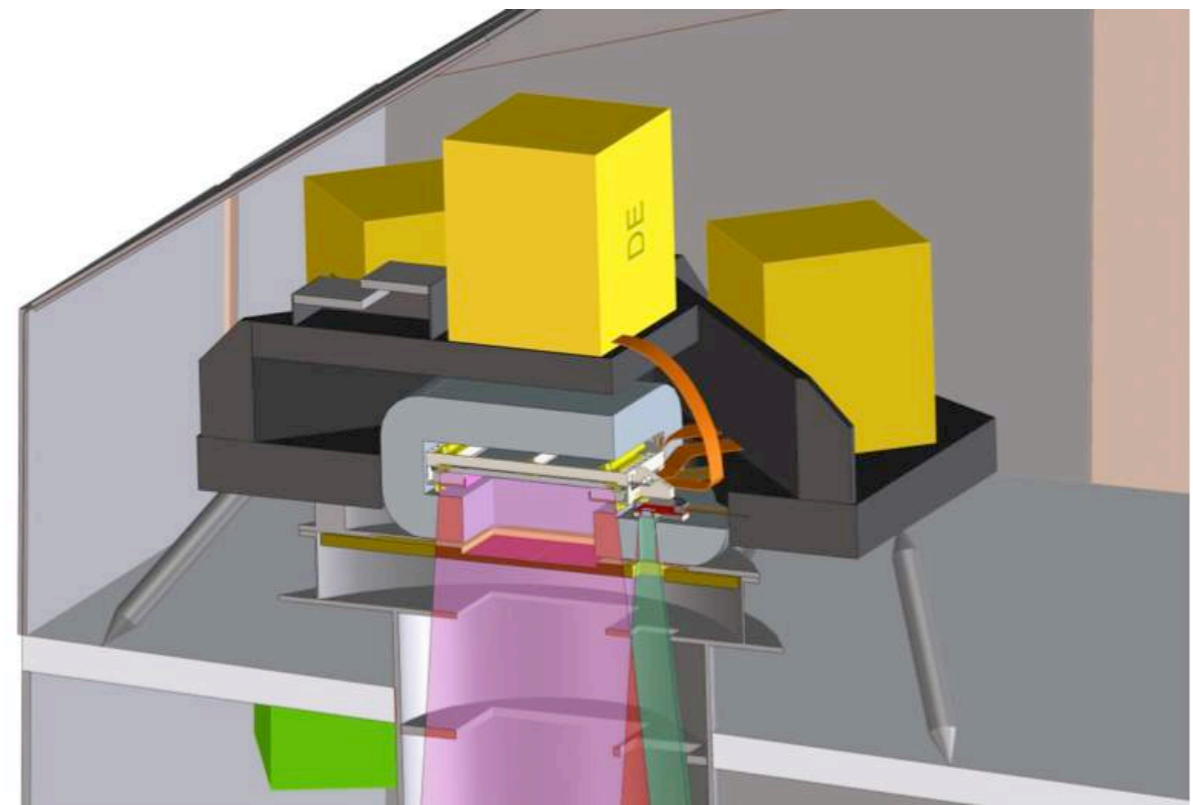
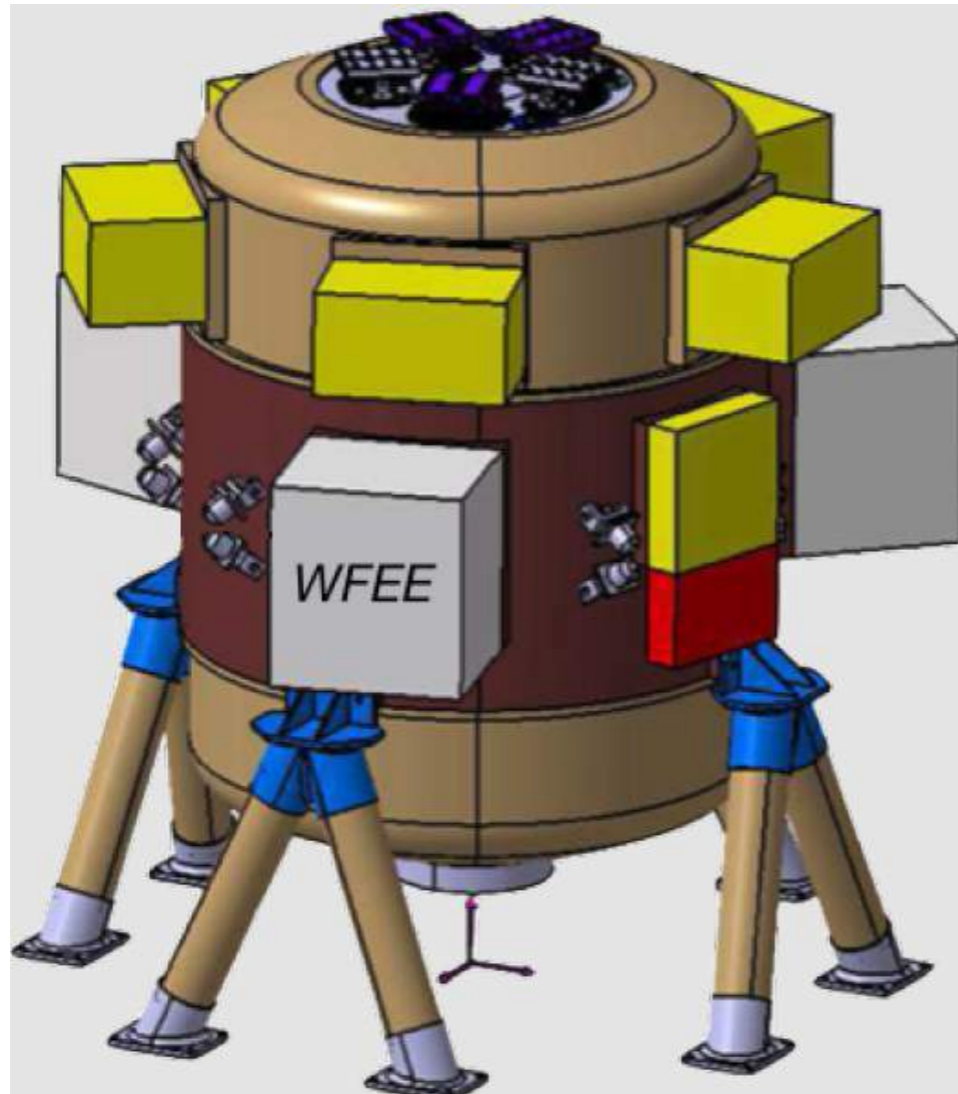
1) X-Ray telescope - 12m focal length, an effective area about 2 m² at 1 keV

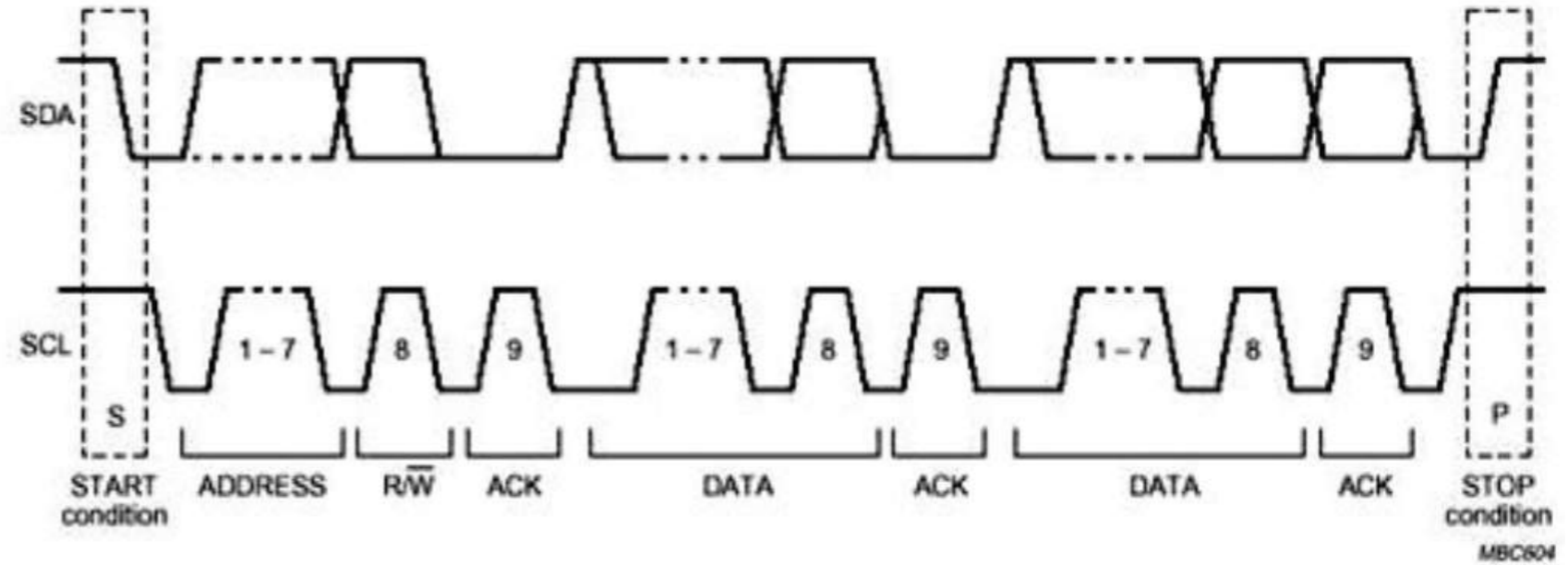
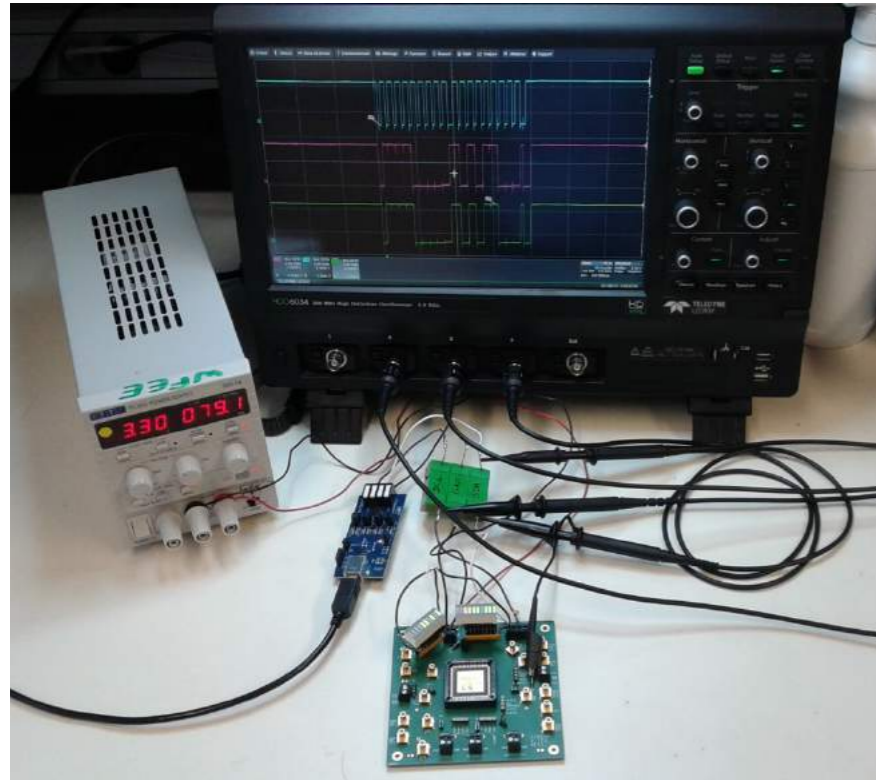
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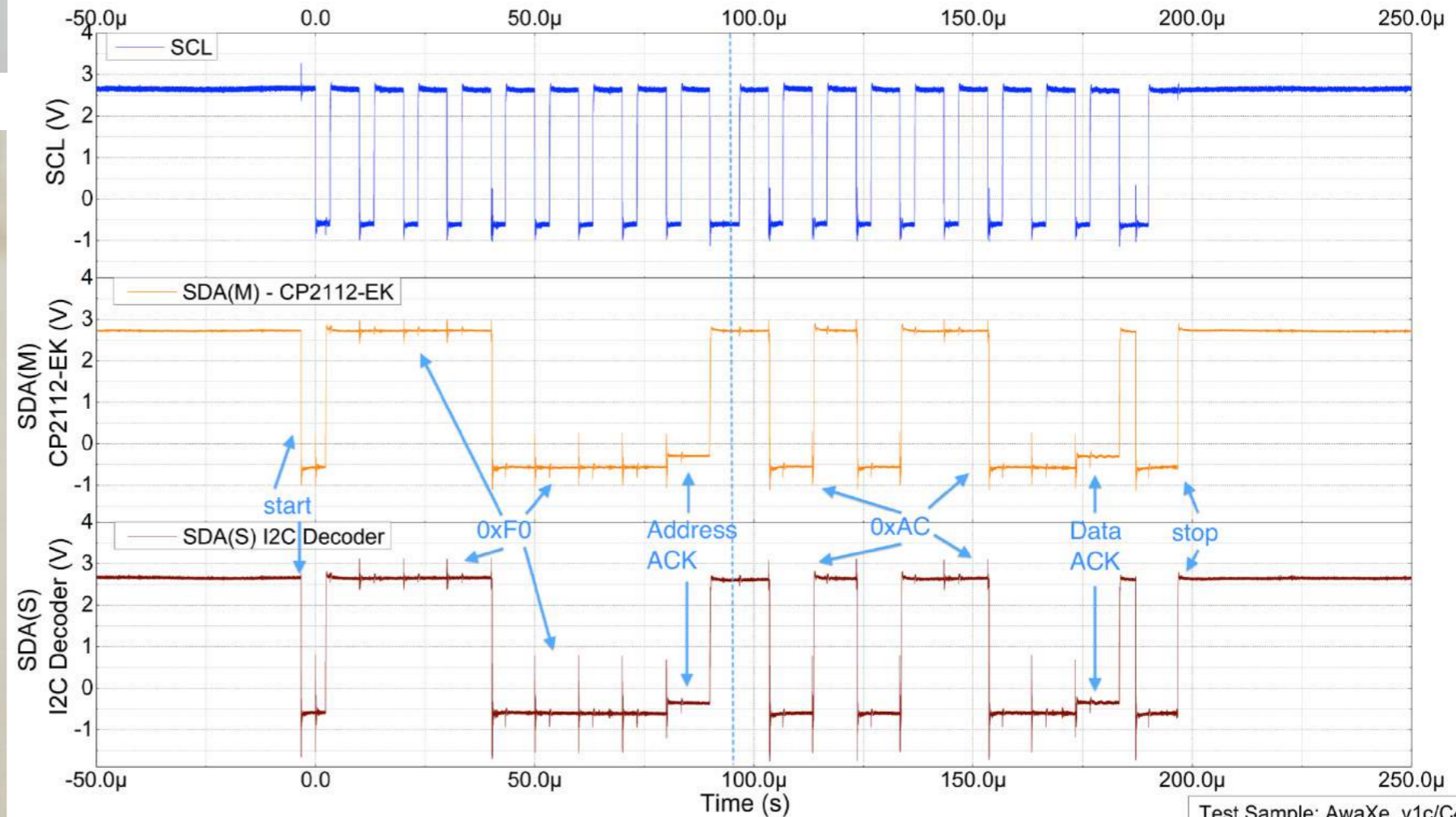
- ❖ 2) X-IFU (X-ray Integral Field Unit) :
Transition Edge Sensors (TES), 2.5 eV high spectral resolution: $E < 7$ keV
- ❖ 5" pixels, field of view 5 arc minutes

- ❖ 3) WFI (Wide Field Imager) for high count rate, large field of view, 0.2-15 keV energy band
- ❖ Silicon-based detector using DEPFET Active Pixel Sensor (APS) technology





I2C Decoder Test - Short SDA and SCL lines (DC Coupling) - with Pull-up Resistors 1kΩ - SCL 100kHz - Data 0xAC



Test Sample: AwaXe_v1c/C4
Test Date: 16/11/2016

